# PLM Industry Summary

Editor: Christine Bennett
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# Company News

## *As Product Complexity Continues to Increase, PLM Systems Will Need Cross-disciplinary Functionality to Satisfy Engineering Requirements, UGS Executive Vice President Chuck Grindstaff Tells Leading PLM Academics*

27 March 2007

Executive Vice President, Chuck Grindstaff, head of products for UGS Corp. said that in the era of ever increasing product complexity, design, engineering, manufacturing, maintenance and repair cycles must be integrated processes in a distributed, multidisciplinary and highly automated environment.

Grindstaff made the statements during his keynote address at the Future of Product Development Conference (http://www.ipk.fraunhofer.de/cirp2007/) being held in Berlin from March 26 to 28.

Grindstaff added that rapid innovation cycles demand reduced decision time. Practitioners from all disciplines must coordinate their decisions early and concurrently. Considerations from requirements, aesthetics, engineering as well as manufacturing must be balanced and reconciled as early and accurately as possible. Domain specific intelligence incorporated into the design digital product development environment is now routinely employed to augment engineering judgments. New tools must extend the automation to a distributed and scalable network of innovation.

UGS has partnered with the Fraunhofer Institute for Production Systems and Design Technology (IPK) (http://www.ipk.fraunhofer.de/en), to conduct research in conjunction with leading automotive original equipment manufacturers (OEMs) from Japan, Germany and USA, on the Powertrain development processes. The goal of the project is to evaluate the current state and working with automotive OEMs,

define a road map for the next generation Powertrain development processes. This research will enable UGS to develop future PLM technology which will assist OEMs to realize the future vision of Powertrain to have an end-to-end solution with complete digitalization.

“Academic research, responsive IT development teams with domain specific knowledge as well as defined and maintained business processes are prerequisites for new successful practices in the future of our industries,” said Grindstaff. “These types of studies are win-win situations for all involved and are effective for all industries. In this case the definition of the next generation process is a win for the OEMs; a clear set of requirements to help create better software is a win for UGS; and the resulting end product that meets the future needs of consumers is win for the industry.”

“To anticipate the next generation product creation process for Powertrain is a first step towards a roadmap of sustainable innovation for the entire industry,” said Professor Frank-L Krause, Fraunhofer Institute for Production Systems and Design Technology. “Virtualization, extending the view to non-mechanical engineering as well as globalisation and cooperation between OEMs and suppliers are essential for future success.”

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### *Autodesk Recognizes Top-Selling Channel Partners*

29 March 2007

At its recent annual channel partner conference, Autodesk, Inc. announced the companies that have been inducted into Platinum Club 2006, an elite group recognized for top sales performance and outstanding customer service in fiscal year 2006.

"The Autodesk Platinum Club comprises a dedicated and talented group of professionals who are dedicated to our mutual customers' benefit," said Steve Blum, Autodesk vice president of Americas Sales. "We are pleased to recognize their work with Autodesk solutions, designing systems and processes that help our customers reduce costs, improve efficiency and foster innovation in the products they manufacture and the buildings and infrastructure they construct."

Autodesk Platinum Club members include channel partners who have exceeded their sales projections, achieved the highest total revenues or vertical product sales or produced the largest overall growth. They also include channel partners who were the leading education, government or distribution partners in their Americas sales region.

**Platinum Club 2006 Winners**

Autodesk Platinum Club 2006 winners in the United States are Advanced Solutions; Applied Software Technology, Inc.; Applied Technology Group, Inc.; Avatech Solutions; CAD Microsolutions; CAD-1, Inc.; CADD Microsystems, Inc.; CADRE Systems, Inc.; D3 Technologies; Dell; Holman's of Nevada; Ideate, Inc.; IMAGINiT Technologies; INCAT Systems, Inc.; JVH Engineering; L.A. CAD, Inc.; M2

Technologies, Inc.; MasterGraphics, Inc.; Microdesk, Inc.; Microsol Resources; PacifiCAD, Inc.; StrucSoft Solutions; The PPI Group; Torcomp, Inc.; and Total CAD Systems.

In Canada, Consortech Solutions Inc.; IMAGINiT Technologies; Solid Caddgroup, Inc; and Solid Engineering Solutions Inc. are members of the Platinum Club 2006.

Latin America winners are Joflan S.A. de C.V.; MAPData Technologia, Informatica e Comercio Ltda.; PARS; and Tecnoglobal.

Platinum Club members were honored at One Team Conference (OTC), Autodesk's annual event for value-added resellers (VARs) of Autodesk software and related services. Themed "Changing the Game," this year's conference equipped thousands of VARs with the tools and insight they need to seize on market opportunity.

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### *Cimatron Opens Two New Offices in China to Meet Growing Demand*

27 March 2007

Cimatron Limited announced the opening of two new offices in China. The new offices in Fujian and Wuhan will join the existing offices in Beijing, Chengdu, Guangzhou, Shanghai, and Wuxi, supporting the growing customer base and accelerating demand for Cimatron's products in China.

"Cimatron's subsidiary in China achieved 80% revenue growth in 2006," said Danny Haran, Cimatron's President and CEO, in his comments on the company's recently announced financial results. "The Chinese market is the fastest growing market for Cimatron, and we continue to invest and expand our operation in this strategic market."

"The Chinese economy continues to expand at a rapid pace, and more tooling and manufacturing operations now realize the need for more advanced and productive CAD/CAM solutions," says Lang Yan, Cimatron's General Manager in China. "The new offices will enable us to better support our rapidly growing customer base and meet the increasing demand for Cimatron's solutions."

Earlier this month, Cimatron China hosted its annual Dealer Conference, an event that brought together the most senior representatives of Cimatron dealers around the country. Over twenty independent dealers are currently authorized to sell and support Cimatron's products in China.

The conference coincided with the launch of a new release of Cimatron's flagship product -- CimatronE 8.0 -- to the Chinese market. The new release has attracted much attention, with many local media representatives attending the event. A localized Chinese version of the product is scheduled to be released later this month.

Ira Bareket, Cimatron's Corporate Vice President of Sales and Marketing, attended the Dealer Conference and remarked: "This conference is a testament to Cimatron's commitment to the Chinese market. Manufacturing activity in the region continues to show strong growth, and local manufacturers are looking for ways to continue and compete in the global arena. It is important that we not only provide them with the technology they need, but also have local resources that can provide first class support to the growing number of manufacturers and toolmakers that are adopting Cimatron's solutions."

For more information, please visit the Cimatron websites at http://www.cimatron.com.cn/ (Chinese) or http://www.cimatron.com (English).

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### *CoCreate 2007 Design Competition: Vote Now; Cast your ballot for your favorite designs by April 13, 2007*

26 March 2007

CoCreate Software, Inc. announced that the public voting period is now open for its 2007 Design Competition.

Over 150 different innovative product entries have been submitted from companies all across the world.

To vote for your favorite design in each category, visit: http://www.cocreate.com/vote.

Votes can be cast through April 13, 2007 with the winners announced soon thereafter.

"This year's design competition theme of innovation is clearly thriving within the product development community and CoCreate's customer base," said William M. Gascoigne, CoCreate CEO. "It is exciting to see how industry innovators are leveraging a Dynamic Modeling based platform to bring new products to market. The entire industry is welcome to visit the amazing variety of customer products showcased on our website. Voting is open to everyone."

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### *Mentor Graphics Announces Winners of its 19th Annual PCB Technology Leadership Awards*

28 March 2007

Mentor Graphics Corporation announced the winners of its 19th Annual PCB Technology Leadership Awards at a banquet in coordination with PCB Design Conference West. The longest running competition of its kind for PCB designers in the EDA industry, this year the program attracted a record number of submissions from countries around the world, including Germany, Switzerland, China, Norway, Singapore, Austria, Canada, Korea, India, Israel, Portugal and the United Kingdom.

Industry experts judged entries in six categories representing a wide variety of fields: PC Computers and Peripherals; Consumer Electronics & Handhelds; Industrial Control, Instrumentation, Security & Medical; Military & Aerospace; Telecommunication Switches, Network Servers, Base Stations and Computer Mainframes; Transportation and Automotive; and Best Design Overall.

“Mentor Graphics is committed to the PCB designer community, and our PCB Technology Leadership Awards program provides the opportunity to showcase the most innovative and talented designers worldwide,” said Henry Potts, vice president and general manager, systems design division, Mentor Graphics. “This year we saw a significant increase in the complexity of the submissions, with designs including high-speed, pin densities and layers, as well as use of advanced PCB fabrication like microvias. This further validates our investment in innovative design technologies, thus enabling designers to overcome these challenges and deliver competitive electronic products, faster.”

This year’s panel of judges included: Pete Waddell, president, UP Media Group; Rick Hartley, industry consultant; David Wiens, director of product development, systems design division, Mentor Graphics; Happy T. Holden, senior technologist, systems design division, Mentor Graphics; and Gary Ferrari, industry consultant.

"Winning the Military & Aerospace category in the industry's primary design competition is a tremendous honor," said Jayson Harames, PCB design engineer, L-3 Communications. "The hybrid switch module was one of my more complex designs, and makes this achievement even more meaningful to me."

This year’s Technology Leadership Awards winner for the Best Overall Design is the PCB design team from Siemens, including: Mr. Helmut Riedl, Mr. Manfred Hofstatter, Mr. Michael Heider and Mr. Alfred Fuchs. The Siemens team’s winning entry is a reconfigurable FPGA-based signal processing platform on PCI-X. This design was created using Mentor Graphics Board Station RE, HyperLynx® and AutoTherm® tools.

Mentor Graphics will honor award winners at a banquet on Wednesday, March 28th, at the Villa Montalvo Center in Saratoga, California.

**2007 Technology Leadership Award Winners**

**Category: Best Overall Design**

Company Name: Siemens

Designer/s: Helmut Riedl, Manfred Hofstatter, Michael Heider and Alfred Fuchs

Design Description: Reconfigurable FPGA-based signal processing

platform

**Category: Consumer Electronics & Handhelds**

Company Name: Qualcomm Inc.

Designer/s: Larry Paul, George Cordero, Mahmoud Azartash, Anil Kukreja, Vinh Nguyen, Andy Green and Vivek Khushoo

Design Description: RUMI II Mobile Station Modem (MSM) chip emulation card

**Category: Industrial Control, Instrumentation, Security & Medical**

Company Name: Gage Applied Technologies Inc.

Designer/s: Chantal Holloway and Guillaume Turgeon

Design Description: Rabbit high-speed digitizers

**Category: Military & Aerospace**

Company Name: L-3 Communications

Designer/s: Jason Harames and Rolf Thompson

Design Description: XFUSION Hybrid Switch Model (HSM) CCA

**Category: PC Computers and Peripherals**

Company Name: Fujitsu-Siemens

Designer/s: Andreas Schaefer, Markus Wicher and Harald Lugert

Design Description: Mainboard for business PCs

**Category: Telecommunication Switches, Network Servers, Base Stations and Computer Mainframes**

Company Name: IBM Zurich Research Laboratory

Designer/s: Peter Dill

Design Description: Controller board for a 64x64 port high-performance optical switch

**Category: Transportation and Automotive**

Company Name: AVL List GmbH

Designer/s: Wolfgang Rinner, Josef Haring, Franz Summerauer and Alfred Poelzi

Design Description: Dual gigabit, Ethernet concentrator (high-speed communication and control interface)

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### *MSC.Software Announces the Appointment of Sam Auriemma as Chief Financial Officer*

29 March 2007

MSC.Software Corporation announced the appointment of Sam Auriemma as the Company's Executive Vice President and Chief Financial Officer (CFO). MSC's former CFO, John Laskey, will retire from the position he has held since October 2004.

Mr. Auriemma is a financial executive with broad accounting experience within the technology industry, including software and services companies. During his career, he has served as CFO for five different companies, ranging in size from $35 million to $500 million. He was most recently Executive Vice President and CFO of FileNet Corporation, which was acquired by IBM in October 2006. Prior to FileNet he was Executive Vice President and CFO for Wonderware Corporation. Prior to Wonderware he was CFO at Locus Computing, Distributed Logic and Applied Circuit Technology.

"Sam is a seasoned software industry veteran whose career has spanned both private and public companies, where he successfully built the financial infrastructures necessary to support growth," said Bill Weyand, CEO and Chairman of MSC.Software. "Sam is a financial leader with an established track record in improving company performance and shareholder value, as evidenced by his career successes at FileNet and Wonderware. Sam's expertise in accounting and controls, SEC reporting, SOX compliance, tax and international finance as well as acquisitions will serve us well as we position MSC for continuous improvement in financial performance in 2007 and beyond.

"John Laskey came out of retirement in late 2004 to guide MSC through a major accounting restatement process and an SEC investigation. Under his tenure we became current with our SEC filings as well as being listed on NASDAQ. I wish to thank John Laskey for his tremendous efforts over the last two and a half years in helping us achieve our goals and wish him well in his retirement," added Mr. Weyand.

Mr. Auriemma will begin his tenure at MSC on April 16, 2007, and Mr. Laskey will remain with the Company until the end of April and assist in the CFO transition. Beginning May 1, 2007, Mr. Laskey will become a consultant to the Company under a consulting agreement that runs until the end of this calendar year.

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### *Open Text Names Gail E. Hamilton to Board of Directors*

27 March 2007

Open Text™ Corporation announced the election of Gail E. Hamilton to its board of directors during Open Text's Annual General Meeting on December 7, 2006. Ms Hamilton is the former executive vice president of Symantec and has over 20 years experience growing leading technology and services businesses in the enterprise market.

"Gail brings with her a wealth of executive management expertise in the software industry," said John Shackleton, President and Chief Executive Officer of Open Text. "Her extensive operational knowledge and deep understanding of enterprise software is a strategic asset to our board."

Most recently Gail Hamilton led a team of over 2,000 employees worldwide at Symantec and had P&L responsibility for the global services and support business. Previously, she led all of Symantec's consumer and enterprise product development, marketing and support. During her five years at Symantec, Ms Hamilton helped steer the company through an aggressive acquisition strategy. Previous to Symantec, she gained extensive management experience at Compaq and Hewlett-Packard Company, as well as Microtec Research.

Gail Hamilton is a member of the board of directors of Ixia (a provider of IP network testing solutions), Washington Group International (an engineering and construction services company) and Surgient (a supplier of virtualization technology). She received both a BSEE from the University of Colorado and an MSEE from Stanford University.

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### *PTC® Achieves Capability Maturity Model Integration (CMMI®) Level 2 For Pro/ENGINEER®*

27 March 2007

PTC announced that the Pro/ENGINEER Product Development and Quality Assurance organization has been appraised as having met the requirements of the Software Engineering Institute's Capability Maturity Model Integration (CMMI) Level 2. PTC is the first vendor to achieve this rating for a 2D or 3D CAD solution. This achievement demonstrates PTC's ongoing commitment to high quality product and the use of best practices for process management and software development.

The Software Engineering Institute (SEI) is a federally funded research and development center sponsored by the U.S. Department of Defense and operated by Carnegie Mellon University. CMMI ratings assist customers in selecting reliable and low-risk suppliers of software products and services.

The Level 2 rating was achieved using an independent Software Capability Evaluation (SCE) involving extensive review and analysis of PTC's software development and project management processes. The PTC evaluation was performed by an SEI-authorized lead evaluator from Software Technology Transition (STT), a software process improvement consulting firm, using the Standard CMMI Appraisal Method for Process Improvement.

According to SEI documentation, the characteristics of an organization operating at a Level 2 rating include the following:

- Customer requirements are managed and processes are planned, performed, measured, and controlled.

- Projects are performed and managed according to their documented plans • Requirements, processes, work products, and services are managed. The status of the work products and the delivery of services are visible to management at defined points.

- Commitments are established among relevant stakeholders and are revised as needed. Work products are reviewed with stakeholders and are controlled. The work products and services satisfy their specified requirements, standards, and objectives.

"The CMMI Level 2 rating for Pro/ENGINEER highlights PTC's ongoing commitment to providing customers with quality products. These efforts are a key component of a broader quality management system which is designed to assure the integrity of our own software development process," said Rich Butler, divisional vice president, R&D operations, PTC. "PTC is committed to continuously improving our own internal processes, ultimately translating into improved software quality for our customers."

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### *SAP Realigns Executive Board Responsibilities*

28 March 2007

SAP AG announced that it will extend the responsibilities of its executive management team to reinforce the company's growth strategy. These changes come with the announcement of the departure of Executive Board member Shai Agassi, who by mutual agreement with the company, will leave to more quickly commit himself to his personal agenda of environmental policy and alternative energy sources and other issues. In making this announcement, SAP confirms its commitment to the company's current product and platform strategy, and its dedication to the success of SAP customers and partners.

"While we regret Shai's decision to leave, we congratulate him on his record of achievement at SAP," said Hasso Plattner, chairman of the SAP Supervisory Board and company founder. "Shai drove the company's successful platform strategy, led innovation that helped SAP grow and continue market leadership, as well as set the stage for the future of business software. I had shared with Shai my plan that he should become successor to Henning Kagermann as a co-CEO for SAP. With the extension of Henning's contract to 2009, it became apparent that Shai was not comfortable committing to a 10- to 15-year period, which was not in keeping with his personal career timeline. Given this, I made the recommendation to the Supervisory Board that we change our plans and now adjust SAP's executive management team responsibilities."

"We have a strong development and product leadership team in place, we've made remarkable progress along the roadmap to enterprise SOA and have a clear vision about new opportunities for volume business in the midmarket," said Henning Kagermann, CEO of SAP AG.

"It has been my distinct honor to take part in the story of SAP these past six years," said Shai Agassi, president of the Product & Technology Group and member of the SAP Executive Board. "I am very proud of our accomplishments and the successful products we have brought to market. The product team will continue down the path under Henning's leadership and I am confident that SAP will continue to lead the enterprise software market for many years to come. I will remember my time at SAP as one of the most satisfying periods of my career, and it has been my great pleasure to work with such outstanding and passionate people at SAP. I look forward to new opportunities, and working on issues that are important to me, including alternative energy and environmental policy issues, as well as the future of Israel."

The SAP Supervisory Board has accepted Shai's resignation effective April 1, 2007. Shai will be retained as a special consultant to the Office of the Chairman of the Supervisory Board on technology, innovation and competitive trends and maintain an office on the company's Palo Alto campus.

**Apotheker Appointed Deputy CEO; Executive Council Formed**

The company announced that Leo Apotheker, president of Customer Solutions & Operations, and member of the Executive Board, will assume the new role of Deputy CEO of SAP AG effective immediately.

SAP also announced the formation of an Executive Council, comprised of the company's corporate officers. Reporting to the Executive Board, the Council will have shared responsibilities for both customer-facing and product strategies, enabling SAP to align with customer needs more quickly, and in support of the company's 2010 growth plan. Underlining the company's commitment to the current product and platform strategy, those executives leading development organizations will now report into Henning Kagermann.

The following executives will report to Henning Kagermann:

- Doug Merritt has been named a Corporate Officer and will lead the development of software for the business user.
- Klaus Kreplin, Corporate Officer, will continue to lead SAP NetWeaver technology.
- Jim Hagemann Snabe, Corporate Officer, will lead development of the SAP Business Suite and industry solutions.
- Michael Kleinemeier, Corporate Officer, will drive collaboration and lead industry business unit priorities.
- Bob Stutz will continue to lead the CRM team.

The following executives will report to Leo Apotheker:

- Global Marketing and Solution Marketing will be combined into a single marketing organization led by Marty Homlish, Corporate Officer. Peter Graf will report to Marty Homlish as his Deputy.
- Hans-Peter Klaey, Corporate Officer, will continue to lead the SME organization, which now encompasses SAP Business One.
- EMEA NEWS / EMEA Central will be combined into one EMEA region led by Ernie Gunst, Corporate Officer, who is responsible for SAP's field operations in that region.
- Bill McDermott, Corporate Officer, will oversee the Americas and the Asia Pacific and Japan regions. Geraldine McBride will continue to lead the APJ region and report to Bill in his expanded role.

- All partner activities -- including independent software vendors, channel, technology partners, service partners and systems integrators - will be led by Zia Yusuf.

SAP stated that the changes were effective April 1, 2007.

The Company will host a call for media and analysts today at 9:00 pm CET /3:00 pm EDT. The call will be webcast live on the Company's website (http://www.sap.com/). Dial-in numbers are as follows:

Dial in: +1-480-629-9562 or +44-20-8515-2301

Replay: +1-303-590-3030 or +44-20-7154-2833 (Replay Access Code: 3718722)

In addition, the Company will host a call for European media on Thursday, March 29th, at 9:00 am CET. Dial-in numbers are as follows:

Dial in: +44-20-8515-2305

Replay: +44-20-7154-2833 (Replay Access Code: 3719047)

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# Events News

### *How Do You Manage Your Innovation or Intellectual Property?*

March 2007

Global consulting & research firm CIMdata and ESTEQ Design are sponsoring two Product Lifecycle Management (PLM) Awareness events in South Africa.

These forums are designed to introduce PLM concepts to high-level executives of South African companies where management of innovation and intellectual property is vital, enabling South Africa to remain competitive in a changing world.

**Gauteng**:

Tuesday, May 15 2007, Montecasino Conference Centre, Fourways, Sandton

**Cape Town**:

Friday, May 18th 2007, BMW Pavilion Conference Centre, V&A Waterfront.

**Click here to view the agenda for this event.**

**Click here to download the flyer for this event in PDF format.**

**Click here to apply for registration for this event.**
**Registration: R1250 (Excl. Vat) per attendee.**
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### *MSC.Software Announces Worldwide Channel Summits*

27 March 2007

MSC.Software Corp. announced its worldwide channel summits, designed to provide channel partners and prospects with extensive training and support on MSC.Software solutions.

The summits will provide opportunities for partners to learn from and interact with key MSC.Software alliance partners including IBM, Microsoft and Hewlett Packard. These alliances provide go-to-market strategies that can greatly benefit channel partners. Forums will be provided for solution sales training and informational support on how MSC.Software channel marketing can assist partners in driving sales. Key MSC.Software customers will showcase how their businesses benefit from implementing MSC.Software solutions.

"We are excited to bring together the collective experience of MSC.Software's channel partners under one roof," said Alf Goebel, vice president of global channels for MSC.Software. "By sharing the wealth of expertise that exists among our alliance partners, channel partners and MSC.Software, we are best able to bring the benefits of virtual product simulation to our customers."

The MSC.Software Channel Summits will take place:

- April 17-19, 2007 - Renaissance Hotel, Salzburg, Austria
- April 24-26, 2007 - Renaissance Okinawa Resort, Okinawa, Japan

For more information or to register, please visit: www.mscsoftware.com.

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### *Real-time 3D Helps to Finally Solve the Mystery of the Great Pyramid of Kheops!*

30 March 2007

Dassault Systèmes (DS) announced that it today held a world premiere unveiling of the scientifically proven Great Pyramid construction theory with its creator, architect Jean-Pierre Houdin.

Dassault Systèmes' real-time 3D solutions enabled Jean-Pierre Houdin to model and explore the pyramid in 3D and run simulations confirming his theory that the pyramid was built from the inside!

The secret of the Great Pyramid, the sole survivor of the Seven Wonders of the World, has fascinated people throughout time. Countless theories exist as to how it was built, but none stands up to analysis. In

1999, Houdin had an insight and decided to devote himself to developing his theory. Eight years of passion and research ensued, whereby he imagined the construction site of Kheops as the first industrial construction site in history. To further refine and test his theory, he called on Dassault Systèmes to help. As part of its "Passion for Innovation" sponsorship programme, DS decided to help Houdin solve the 4,500-year-old mystery with its real-time 3D solutions.

**Real-time 3D at the service of history and science**

DS's real-time 3D solutions allowed Houdin to establish the first theory ever explaining the construction of the Great Pyramid from start to finish. The theory is founded on three foundations: the use of an outside ramp to build the first 43 metres of the pyramid; the use of an internal spiral ramp running behind the faces of the pyramid to complete the construction; and the use of the Great Gallery to accommodate an ingenious system of counterweights to lift the heavy granite ceiling rafters (up to 63 tonnes) in the King's Funeral Chamber.

"Jean-Pierre Houdin's theory is not only interesting; it is coherent and revolutionary. Take the builders of that time seriously, he sees them as grand masters of construction, as real engineers," declares Egyptologist and pyramid specialist Rainer Stadelmann, ex-director of the German Institute of Archaeology in Cairo. Bob Brier, PhD, Egyptologist and world-renowned expert in the field of mummies adds: "Half-baked theories have been put forward about the Great Pyramid and until now none passed the test of sustained analysis. Jean-Pierre Houdin's theory is worth examining simply because of his rigorously scientific approach, which he supports with a large volume of field-based evidence." Both experts will accompany Houdin on a scientific expedition to the site.

Other participants in the March 30 conference include: Hui Duong Bui, member of the French Science Academy and research director at Poytechnique, who in 1986 conducted onsite Kheops microgravimetry measurements for the EDF Foundation; Marc Buonomo, project manager for Eiffel and the Millau viaduct; and Craig B. Smith, who has studied the construction of the Kheops pyramid in the light of modern project management techniques.

The final step for Houdin and Dassault Systèmes will be to prove the theory in real-life with non-invasive verification techniques conducted on the Kheops site.

The largest real-time 3D virtual reality auditorium in the world, a first for Dassault Systèmes and the Géode

Seven computers running Dassault Systèmes' 3D Virtools solutions are linked in a network to recreate the Kheops construction site in 3D, exactly as it was 4,500 years ago. The system allows the presenter to move about the virtual site freely in response to the audience's questions. This is a first, linking the real and virtual worlds via an immersive, interactive 3D experience.

**Real-time 3D tools. A new era in communication**

The event at the Géode is more than a simple demonstration. It marks a revolution, positioning real-time 3D as the communications medium of the 21st century. The universal language of 3D fosters information sharing: today's conference and the www.3ds.com/khufu website showcase the same real-time 3D technologies, enabling people all over the world to access the heart of the pyramid at will and participate in the revelation of Houdin's theory.

Dassault Systèmes has always been ahead of the times regarding 3D and its usage, with innovative applications in domains such as science, research, education and archaeology. "The Kheops event demonstrates the diversity of applications possible with "3D For All", our strategy designed to benefit the general public's daily lives with realistic interactive 3D experiences," explains Dominique Florack, senior executive vice president, Products R&D, Dassault Systèmes.

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### *Save the Date! UGS Open House op 21 Mei 2007*

March 2007

UGS announces Open House 2007, 21 mei 2007, Chassé Theater Breda, L'Arte Synergetica – de ultieme PLM ervaring.

Twee nieuwe product releases, gerenommeerde gastsprekers en de alom gekende hoogstaande break-outsessions overgoten met een saus van show en entertainment

Ingrediënten die van het Open House 2007 de ultieme PLM-ervaring zullen maken.

L'Arte Synergetica, want 1 + 1 = meer dan 2

Schrijf deze datum nu reeds in uw agenda. Meer binnenkort in uw brievenbus.

Voorregistratie Open House 2007Registreer u nu en wij houden u op de hoogte over het evenement! Klik hier voor het invulformulier

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### *Sequence Low-Power Experts Highlight TSMC Symposiums*

27 March 2007

TSMC symposiums bring together the brightest lights in design and manufacturing, including Sequence Design, this year exhibiting at all three events: April 10, San Jose; April 13, Boston; and April 16, Austin.

Sequence experts will be on hand to discuss the latest and greatest power-saving design technologies, including RTL power analysis, clock power analysis, mixed-voltage design, power-grid optimization, and much more.

"This is the ideal place to meet designers working on the most advanced designs and process technologies," said Holly Stump, Sequence vice president of marketing. "We're looking forward to continuing our dialog on low-power design at the TSMC Symposiums."

Sequence Spotlight Products

Sequence's silicon-aware PowerTheater 65 is the industry's first RTL power analysis and management solution, with physical-design features to ensure results that closely relate to real silicon. It has recently

enhanced its singular ability to accurately estimate and reduce power at RTL with silicon-aware features for voltage islands, mixed voltage threshold, power gating, and clock gating.

The Cool Products family – CoolTime, CoolPower, and CoolCheck – accelerate design closure times by preventing time-consuming iterations between separate timing, SI, power analysis and optimization tools. In addition, CoolProducts help reduce power and ensure power grid integrity to prevent power-related problems.

The Columbus extraction product family is both a foundation for the company's RTL-to-silicon, power-aware SoC design tools and the industry's leading RLC parasitic extraction tool for high-performance digital (Columbus Turbo) and analog/mixed-signal (Columbus AMS) designs.

**TSMC Symposiums**

TSMC's "The Proven Path to Success" symposiums give attendees access to the technologies, design services, and backend services necessary to drive market share and revenue growth. Focus areas include breaking news on 45nm and 65nm advanced technologies, DFM programs, TSMC libraries and IP, and more. For additional information: http://www.tsmc.com/.

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### *Si2 Announces the Tenth OpenAccess+ Conference*

27 March 2007

The Silicon Integration Initiative (Si2) announced that its tenth OpenAccess+ Conference will be held on April 3, 2007, at Sun Microsystems' Santa Clara Conference Center in Santa Clara, California. The Conference will feature speakers and demonstrations from several of the industry's leading semiconductor and electronic-design automation (EDA) companies. Industry veteran Mark Templeton will be providing the keynote address.

The 10th OpenAccess+ Conference will focus on progress in achieving interoperability, a fundamental promise of OpenAccess. Important EDA tool releases and progress by end-users using OpenAccess indicates that the promise of interoperability is now a reality. The conference will explore new advances in OpenAccess adoption, as well as related advances in modeling of process variations which are essential for 65nm and lower technology nodes. Speakers will include representatives from Sun Microsystems, LSI, AMI Semiconductor, Renesas, Hewlett-Packard, ARM, Cadence, Altos, Extreme DA, CiraNova, Silicon Navigator, and Mentor Graphics. Finally, there will be a number of companies who will be providing real-life evidence of the value of OpenAccess through demonstrations of their tools on the OpenAccess reference implementation.

For more information, the full agenda, and to register for the conference, visit http://www.si2.org/?page=809.

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### *UGS Strengthens Channel Sales Efforts In Asia Pacific at Go!2007 Conference*

28 March 2007

UGS Corp. announced its increased momentum of its channel sales efforts in Asia Pacific with the conclusion of the Go!2007 Conference that attracted more than 700 attendees throughout the region.

The conference, themed 'Own the Road,' provided UGS' partners with the foundation to grow their business through 2007 with a consolidation of multiple training events and a briefing on updates to the UGS Channel Partner Program. UGS also shared its plans for continued growth in the mid-market space as well as new enhancements for UGS' NX™, Teamcenter® and Tecnomatix™ product suites.

Awards were presented to key channel partners including 16 top performers and numerous technical excellence awards. The Top Asia Pacific Channel Partner Award went to ISID TechnoSolutions, Ltd. (ISID-TS) from Japan while PDS Technology from China won Top New Partner Award "Rookie of the Year." ISID-TS has been a UGS Channel Partner for more than 24 years and has provided great support for a number of key customers in Japan. PDS Technology joined the partner program April 2006

"With the strategic support from UGS, ISID-TS is most pleased to win the Top Asia Pacific Channel Partner award," said Norio Tayama, executive vice president and COO of ISID-TS. "This will definitely be a key motivator for an even more successful 2007. PLM industry is gaining greater attention in the Japan market and we are excited to take part in developing this exciting market momentum."

"This event helped us to build a stronger partner network with UGS," said Li Zhiyong, president, PDS Technology. "Especially with a focus in Asia Pacific, we expect this to help our business greatly and look forward to more of such collaborations in the coming year. We are very happy to have become a member of extended UGS family."

"Our Channel Partners have the ability of leveraging and representing the entire portfolio of UGS products and services based on their core competencies, industry specific sales and technical resources, business plan, and specific geographic knowledge - they are key to our commitment to never letting a customer fail,." said Tony Jolly, vice president of Channels and SI Alliances for Asia Pacific, UGS. "UGS strives to offer our partners the industry expertise and training they need to effectively align their resources to get the most from their investment."

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### *VISTAGY Announces ING Renault F1 Team Technical Director Bob Bell to Present at JEC Composites Show 2007*

26 March 2007

VISTAGY, Inc. announced that ING Renault F1 Team Technical Director Bob Bell will present at the VISTAGY stand (#B36) during the JEC Composites Show 2007 in Paris, France on Tuesday, April 3, 2007. Mr. Bell will outline how the team's partnership with VISTAGY helps it meet the production schedules and complex design challenges related to developing composite parts for its racecars. VISTAGY will be in attendance at the event from April 3 – 5 at the Paris Expo, Porte de Versailles and will feature at its stand the ING Renault F1 Team racecar, presentations by ING Renault F1 Team

executives, and the latest versions of its FiberSIM® composites engineering software and Airframe Design Environment™ (ADE) software for developing airframe assemblies. VISTAGY executives will also deliver informative presentations during the show.

As Technical Director, Mr. Bell is charged with all aspects of the composites design and manufacturing strategy for the ING Renault F1 Team racecars. The team has used VISTAGY's FiberSIM software to design and manufacture composite components on four generations of racecars, including the R25 and R26 cars that won back-to-back Federation Internationale de l'Automobile (FIA) Formula One Drivers' and Constructors' World Championships in 2005 and 2006. Mr. Bell will give the following presentations at the VISTAGY stand:

**"VISTAGY's Contribution to the World Champion ING Renault F1 Team"**

***Tuesday, April 3: 11:00 and 16:00***

In addition, ING Renault F1 Team senior CAE engineer Ian Goddard will provide technical presentations on the use of FiberSIM for F1 composites design at the VISTAGY stand on the following dates:

- *Wednesday, April 4: 10:30, 13:30 and 16:30*
- *Thursday, April 5: 9:30, 11:30 and 14:30*

VISTAGY executives have also been selected to deliver the following presentations at JEC and the accompanying SAMPE Europe Conference, which takes place at a nearby hotel in cooperation with JEC:

**"Streamlining Global Airframe Assembly with Model-based Composites Design Processes"**

Presented by Dr. Olivier Guillermin, VISTAGY director of product & market strategy

***Thursday, April 5 at 10:30***

JEC Composites Show 2007 - Aeronautics End-users Forum

Paris Expo, Porte de Versailles, Espace 2000, First floor, Hall 1

**"Model-based Definition for Composites Design Drives ING Renault F1 Team to Back-to-back Championships"**

Presented by Mr. Peter Ungaro, VISTAGY director of applications engineering

***Wednesday, April 4 at 16:20***

SAMPE Europe Conference 2007

Hotel Mercure Paris Porte de Versailles Expo, Session 11B

In addition to featuring FiberSIM software for F1 racecar design at its stand, VISTAGY will showcase its Airframe Design Environment software, which collectively with FiberSIM delivers the industry's only complete 3D global engineering environment specifically for developing airframes. The software, which is tightly integrated into major commercial CAD systems, supports the entire end-to-end airframe development process—from conceptual composites design through detailed design, manufacturing, assembly and quality assurance. For the first time, manufacturers can utilize a single, seamless engineering platform that supports all design methodologies and phases of airframe development in order to more quickly, accurately, and cost-effectively create the world's most innovative composite products.

For more information on the ING Renault F1 Team, http://www.ing-renaultf1.com.

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# Financial News

### *CENIT Annual Report 2006*

27 March 2007

For CENIT 2006 was characterised primarily by expanding international business and related investments in further profitable growth. Higher marketing and sales expenditure resulted particularly from the successful expansion of the US business and higher revenues from the sale of CENIT software via distribution partners such as SAP, IBM/FileNet and Dassault Systèmes. In 2006, the number of employees across the group again increased by 10% and now totals 576. The foundation of a new company in Romania in 2006 is also a necessary investment to improve the company's competitive ability. The basis for figures for 2006 is preparing the future of CENIT and its strategic alignment.

In financial year 2006, CENIT generated group sales of € 82.4 million (2005: € 74.3 million / 11%). The services area again generated strong growth. This was accompanied by an extremely positive development in selling CENIT proprietary software. Gross profit rose again, by 13% to € 59 million (2005: € 52.1 million). EBITDA reached € 11.1 million (2005: € 10.2 million / 9%). In the reporting period, EBIT moved up from € 9.4 million by 9% to € 10.2 million. CENIT will conclude an extremely important and positive year with EBT of € 10 million (2005: € 9.1 million / 10%) and group earnings per share (EPS) of € 1.00 (2005 adjusted: € 0.81). Earnings per share include a positive non-recurring effect of € 699 thousand from one-off corporation tax income.

The good earnings situation positively impacted the group assets situation. As of the reporting date, equity totalled € 24.3 million (2005: € 19.6 million), resulting in an equity ratio of 62% (2005: 58%). As of the balance sheet date, bank balances and securities totalled € 18.7 million (2005: € 20.8 million).

Cash flow from operating activities was € 10.3 million (2005: € 8.9 million), with a free cash flow of € 1.6 million being reached (2005: € 4.4 million).

**Dividend proposal**

The Executive Board and Supervisory Board will propose the shareholders' meeting the distribution of a dividend of EUR 0.50 to the shareholders and the transfer of € 3.5 million to revenue reserves.

**Breakdown of sales**

In the Product Lifecycle Management segment, CENIT achieved sales of € 53.9 million (2005: € 48.9 million / 10%) and an EBIT of € 6.9 million (2005: € 6.4 million / 8%). The Enterprise Content Management segment posted sales of € 28.5 million (2005: € 25.4 million/ 12%) and an EBIT of € 3.3 million (2005: € 3.0 million / 10%).

Sales with CENIT software increased by 47% to € 11.2 million. Now 14% of sales are achieved with CENIT proprietary software. In the previous year, the figure was € 7.7 million, approximately 10% of total sales. The business with third-party software also increased, by 13% to € 9.4 million (2005: € 8.3 million). The development in the services area is equally pleasing. Sales again increased, by 9% to € 46.8 million (2005: € 42.8 million). The hardware business declined by 3% to €15 million (2005: € 15.5 million).

**Foreign subsidiaries**

In the past financial year, CENIT (Schweiz) AG generated sales of € 2.6 million (2005: € 1.3 million) and an EBIT of € 1.1 million (2005: € 56 thousand). The software solution FileNet Systems Monitoring was the key driver for results and sales.

On sales of €4.7 million (2005: € 1.7 million), CENIT North America Inc. posted an EBIT of € 0.4 million (2005: € 0.2 million). With a total of 17 employees and a positive earnings contribution already been made to the group, the decision of the Executive Board to develop the software and consultancy business in the USA in a rigorous fashion was confirmed on a sustained basis.

In the 2006 financial year, CENIT also founded a subsidiary in Romania. In the application management and software development area, CENIT is now able to face the market on a more competitive basis. The company is being developed and is to be further extended in 2007. Smaller initial projects were already processed in 2006. On sales of € 0.03 million, CENIT SRL generated an EBIT of € 0.01 million.

**Order situation**

As of December 31, 2006 the order backlog for the group was € 18.2 million (2005: € 19.3 million) and incoming orders in 2006 totalled approximately € 84.8 million (2005: € 79.6 million). Overall, the share of new customers increased to 7% in 2006.

**Outlook**

CENIT has established the objective to increase the share of proprietary software in total sales to between 20 and 30 percent over the next two to three years. To do this, it is necessary to expand the international distribution channel further. A fundamental element of this strategic focus is the existing distribution and software development cooperation with Dassault Systèmes, SAP, FileNet and IBM. For group sales we expect growth in line with the market in 2007 and 2008. In particular, increasing revenues for the sale of CENIT proprietary software and the worldwide distribution cooperation for the FileNet System Monitoring solution will contribute to this.

With the strategic alignment on the attractive markets for Product Lifecycle Management, Enterprise Content Management and Application Management Outsourcing and concentration on our core competencies, CENIT will also invest strongly in the consultancy and software market in 2007 and 2008. We anticipate that in 2007 and 2008 all segments will contribute to improving further the operating performance of the group. Our market and customer contacts in all segments are a good basis for offering our business partners supplementary products and services. Added to this is a consistent alignment to the world market and the expansion of our USA activities, particularly in the software area together with SAP and Dassault Systémes. The development of our subsidiary for software development and application management outsourcing services in Rumania in line with the market is a further important step to improve competitive strength at CENIT.

We continue to expect a positive market environment in our relevant markets. We want to take this opportunity to gain further market share. For this reason, CENIT wants to increase its staffing levels by 10% again in 2007. Should the trend continue, then a further expansion in staff numbers is to be expected in 2008. We want to become stronger, particularly in the consultancy business and in bespoke software development as well as advancing our US business with American staff.

The expansion of the US business initiated in 2006 brought with it a strong increase in marketing and sales expenses. This will again be the case in 2007 as the market opportunities in the USA are stronger than the possible risks.

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### *Centric Software Milestones Show Market Acceptance of Product Intelligence For Global New Product Development and Construction Centric Software Announces Second Year of Record Growth*

26 March 2007

Centric Software announced its second consecutive year of record growth and expansion in key market sectors including consumer goods, apparel and retail, life sciences, and architecture/engineering and construction (AEC). Key factors contributing to the revenue growth are an expanded software portfolio, with four new Product Intelligence applications, and the release of v6.0 of Centric InSight, the only out-of-the-box application for intelligent search and discovery of engineering and technical content.

"Our strong growth last year derives in part from the strength and loyalty of our solid customer base. The second significant growth factor—from new business—proves that a new market exists for Product Intelligence applications that span and leverage traditional ERP, PLM, and many other standalone enterprise applications," said Chris Groves, chief executive officer, Centric Software. "Product Intelligence applications address the problems inherent when working with global teams and distributed information, such as collaborative product development with overseas suppliers for fast-moving consumer goods, sourcing private label or branded products overseas, and visibility across multiple simultaneous global programs and projects. Our early start in this market and current momentum point to strong growth in our next fiscal year."

**Centric Software Highlights for Most Recent Fiscal Year**

- 300% increase in year-over-year new license revenue in Consumer and AEC markets
- Surpassed 40,000 users in several industry verticals, managing more than $10B in new products and projects
- Expanded regional and vertical partnerships:
    - Invensys and GxP in Life Sciences
    - Neoris and AEC in Apparel, Retail and Consumer Goods
    - IBM and PCO in Auto/Aero
- Architecture validated by IBM and Microsoft:
    - Certified as "Ready for SOA" by IBM
    - Awarded Microsoft Certified Partner
- Introduced Product Intelligence™ and new Product Intelligence applications for apparel management, global sourcing and multi-team programs
- Launched Centric Insight –the only intelligent search and dynamic discovery application for product and technical information, including information embedded in sources such as PLM, PDM, and ERP systems, office applications, email and CAD drawings

"This new market for Product Intelligence applications is characterized by companies with global teams using multiple source applications. These teams want to continue to leverage existing applications and existing business processes, rather than undertaking a massive, disruptive re-vaulting of information. Other customers for PI applications recognize that all information will never be in one place, so that

rather than revaulting, these companies choose to find and connect to the information where it exists," continued Groves.

For more information on Centric Software, visit: http://www.centricsoftware.com/

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### *Delcam Sets New Sales Record in 2006*

30 March 2007

During 2006, CADCAM developer Delcam again achieved record sales, with a further acceleration in the growth in sales that has been seen in recent years. Group sales for the year to 31 December 2006 rose by 14% to £26.7 million from £23.5 million in 2005. Profit before tax increased by 9.6% to £2.56 million from £2.34 million. These record results were driven by good growth in software licence sales in the core Power Solution range of software and by additional revenue from our newer software ranges, FeatureCAM, which was acquired in July 2005, and PartMaker, which was acquired in July 2006.

Commenting on the results, Delcam Chairman Tom Kinsey said, "The Group made good progress over the year. We continue to ensure that our products remain industry-leading through significant investment in research and development and believe this policy will ensure higher sales over the longer term. Our R&D investment over the year was £7.3 million (2005: £6.5 million) and we released improved versions of all of our main software products during the period. The value that our customers place in these enhancements is reflected in the record levels of income from maintenance contracts."

Mr. Kinsey also highlighted the importance of the company's broadening customer base. "Several years ago, we began a diversification strategy to reduce our dependence on the mould and die industry," he said. "It is particularly pleasing to report our progress in the aerospace industry. As well as significantly increasing our software sales in this sector, our Professional Services Group has been able to develop valuable business with leading engine and airframe manufacturers. The dental industry is another area where we have had initial success and expect to see further growth following the introduction of Dentmill, a dedicated version for the sector of our PowerMILL CAM program."

View full report here (pdf)

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### *Renishaw Placing*

30 March 2007

Delcam announced today that it had conditionally raised £6,096,208 before expenses through a placing of 1,524,052 new Ordinary Shares with Renishaw at £4.00 per share. The net proceeds will be used to fund the expansion of the business and for further investment in the development, sales and support of Delcam's products.

**Reasons for the Placing, use of funds and dividend policy**

The Directors believe that the Company's growth in sales can be sustained and built upon by working more closely with Renishaw.

Renishaw was established in 1973, is listed on the Official List of the United Kingdom Listing Authority and is a leading provider of metrology and spectroscopy solutions to manufacturers and researchers. It has been awarded eleven Queen's Awards for Export Achievement, Technological Achievement and Enterprise. In the year to 30 June 2006, Renishaw generated turnover of £175.8 million and profit before tax of £38.1 million.

Renishaw and Delcam have worked together for many years and share common metrology interests and customers. We believe closer cooperation with Renishaw will enhance the sales of both companies. This would be achieved by initiatives such as the agreement recently entered into with Renishaw for the development of software to support the application of Renishaw's new probes.

As a commitment to a closer working relationship, Renishaw has conditionally agreed to subscribe for the Placing Shares, which will represent approximately 20 per cent of Delcam's enlarged issued Ordinary Share capital. The proceeds of the Placing will be used to fund Delcam's expansion organically and by acquisition and to invest in the development, sales, development and support of Delcam's products.

After completion of the Placing, it is the intention of the Directors to review the Company's dividend policy to ensure that the level of dividend per Ordinary Share is not adversely affected by the Placing.

**Placing and Renishaw director**

The Company has conditionally raised £6,096,208 before expenses through a placing of 1,524,052 new Ordinary Shares with Renishaw at the Placing Price. The Placing is conditional on the passing of the Resolutions and the admission of the Placing Shares to trading on AIM. The Placing is also conditional on there being no material adverse change in the financial or trading position or prospects of the Company between the date of this letter and completion of the Placing.

The Company has been in discussions with Renishaw for some time in relation to these proposals and the Company's share price has risen considerably over that period. The average middle market price for the Company's shares in December 2006 was 310p and this had risen to 416.5p on 29 March 2007, a rise of 34.4%. The Placing Price of £4.00 represents a discount to the closing middle market price of the Company's shares on 29 March 2007 of 4%.

The Placing Shares will not qualify for the final dividend for the financial year ended 31 December 2006 but will otherwise rank pari passu in all respects with the existing Ordinary Shares.

Application will be made to the London Stock Exchange for admission of the Placing Shares to trading on AIM and, subject to the passing of the Resolutions at the EGM, the Placing Shares are expected to be admitted on 24 April 2007.

Delcam has agreed with Renishaw that, for so long as Renishaw holds more than 15 per cent of the Company's Ordinary Share capital, it will be entitled to nominate a director for appointment to the Board. The nominated candidate will be subject to the approval of the Directors (which will not be unreasonably withheld) and assessment of the candidate by the Company's nominated adviser in accordance with the AIM Rules.

Delcam has also agreed that it will not make a purchase of its own shares or reduce its share capital to an extent which would cause Renishaw's holding of Ordinary Shares to exceed 29.99% of the Company's Ordinary Share capital from time to time, unless the Panel on Takeovers and Mergers first waives Renishaw's obligation to make an offer for the Company in those circumstances.

Renishaw has agreed with the Company that:

- for five years from completion of the Placing and subject to certain exceptions, it will not acquire further shares in the Company which would result in it holding more than 20 per cent of the Company's Ordinary share capital from time to time without the agreement of the Board;
- it will not exercise the voting rights attaching to the Placing Shares on any resolution to appoint or remove a director of the Company other than Renishaw's nominated director (unless it elects to vote in accordance with a written voting recommendation made to Shareholders by the Board or to re-elect a director retiring by rotation and offering himself for re-election); and
- for five years from completion of the Placing and subject to certain exceptions, it will only dispose of the Placing Shares through the Company's brokers from time to time in order to maintain an orderly market in the Company's shares.

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# Implementation Investments

### *A.O. Smith Electrical Products Company Selects Dassault Systèmes PLM Solutions to Streamline Global Product Development*

28 March 2007

Dassault Systèmes announced that A.O. Smith Electrical Products Company, a $1 billion division of A.O. Smith Corp. has purchased the ENOVIA MatrixOne PLM solution. ENOVIA MatrixOne will help A. O. Smith Electrical Products Company integrate global design, manufacturing and resource planning to deliver products more quickly to market. The company is one of North America's largest manufacturers of electric motors for residential, commercial, and industrial applications.

"We're adopting ENOVIA MatrixOne as the technology foundation of a comprehensive PLM strategy to optimize our global engineering organization, which spans the United States, Mexico and China," said Steve Robbins, A.O. Smith's vice president of engineering and information technology. "We aim to drive costs out of our product introduction efforts, gain real-time control of multiple projects, and make decisions that most benefit our customers, partners, suppliers and shareholders."

The company selected the ENOVIA MatrixOne PLM solution to implement a wide variety of high-priority business initiatives, including:

- Leveraging global design in one integrated solution;
- Centralization of product data for universal accessibility and reuse;
- Deployment of common development systems and processes;
- Efficient management of product changes; and

- Sharing of data among all enterprise systems.

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### *Autodesk Surpasses Eight Million Licensed Users*

29 March 2007

Autodesk, Inc. announced that it has surpassed eight million licenses for its software applications. The record parallels continued growth for its 2D software, new software licenses in emerging economies as well as robust revenue increases in Autodesk's model-based 3D software.

In the fourth quarter of fiscal 2007 alone, Autodesk shipped more than 47,000 commercial seats of its 3D applications including Autodesk Inventor products, Civil 3D software and software products based on the Revit platform. Combined revenues from these model-based design tools increased 40 percent over the fourth quarter of fiscal 2006 to a record $121 million, or 24 percent of total revenues in the quarter. License growth in the fourth quarter of the fiscal year also reflected a 44 percent increase in revenues from emerging economies in Asia Pacific, Eastern Europe, the Middle East and Latin America.

"Eight million users around the world continue to depend on Autodesk's industry-leading solutions, and we are pleased to see that growth stimulated by more customers experiencing the benefits of model-based 3D design," said Carl Bass, president and CEO, Autodesk. "Our 3D solutions let customers from the manufacturing, building and construction, and media and entertainment industries visualize, simulate and analyze the real-world performance of concepts, enabling shorter time to market, a reduction in production costs and improved quality and design."

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### *Autoweb Awarded Three-Year Contract in New Business*

26 March 2007

Autoweb, is expanding its presence in the aerospace industry with a contract award from a major aerospace supplier.

The three-year agreement will automate the key processes used by the aerospace supplier to manage the translation and exchange of computer-aided design (CAD) data within its enterprise and with its customers and suppliers. Autoweb's Fusion-DX and Global Supplier Network (GSN) Services will replace the supplier's current manually-orientated processes to deliver significant improvements and waste reductions.

The aerospace supplier will incorporate Autoweb's solution over eight global sites, which will reduce duplicate work and inefficiencies. The solution will be integrated with the company's PLM Teamcenter

Engineering and NX CAD translation solutions which facilitate end-to-end management of engineering data exchanges via Autoweb's GSN network.

"With these solutions working together, the client is expected to significantly increase productivity at all of their global sites," said Martyn Davies, vice president of European Operations for Autoweb. "By employing Autoweb's software as a service model, the client will significantly reduce costs associated with managing these services internally."

The Autoweb solution connects clients with their customers and suppliers via the GSN network -- allowing for a two-way exchange of CAD data -- which is simple and highly secure.

"All of our tools are designed to provide our valued original equipment manufacturer (OEM) customers and their suppliers with the ability to easily expand their use globally," Davies noted.

Autoweb will exhibit during the 2007 Society of British Aerospace Companies (SBAC) conference on March 29 in Manchester, United Kingdom. Autoweb representatives who plan to attend are Martyn Davies, Vice President of European Operations, and Mark Embra, Sales Executive.

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### *Catalog Data Solutions Adopted by Buckeye Fasteners Company*

27 March 2007

Catalog Data Solutions (CDS) announced that Buckeye Fasteners has adopted its CAD model download solution.

Buckeye Fasteners Inc., a subsidiary of Fastener's Industries Inc., stocks and distributes fasteners from leading manufacturers including Brainard Rivet Co., Captive Fastener Corp., Con-Torq Div., Crest Products Inc., Decker Manufacturing Corp., Miniature Nut and Screw Co., The Ohio Nut and Bolt Co., Stafast Products, Inc. and more.

Responding to customer requests for CAD models of its products, Buckeye Fasteners decided to offer 3D CAD models of fasteners for download from its web site. "We have learned that when a customer downloads a CAD drawing, we will save them time and they will likely purchase the product," said Larry Kelly, Sales Manager, Buckeye Fasteners. "With the addition of 2D/3D CAD drawings to our website, we are meeting the needs of our customers and we expect our sales to increase as a result."

"We are delighted to have been selected by Buckeye Fasteners for our leading online CAD model download solution, lead tracking system and affordable CAD services", said John Major, CEO Catalog Data Solutions, "online 3D models are an important sales and marketing tool for all industrial suppliers and distributors. With many customers moving from 2D to 3D CAD systems providing online 3D CAD model downloads often 'locks' products into a design so suppliers later benefit from the sales success of

that design. Suppliers without 3D models on their website are at risk of losing customers to their competition who do offer 3D models".

Studies show that over 90% of designers and engineers now use the Internet to locate components for their new designs. Catalog Data Solutions helps industrial suppliers and distributors grow sales and strengthen customer loyalty through interactive online catalogs, ecommerce, 3D CAD model delivery and product configurator solutions.

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### *Chengdu Aircraft and Dassault Systèmes Take to the Skies with Composites*

29 March 2007

Dassault Systèmes (DS) announced that Chengdu Aircraft Industrial Group, a major Chinese supplier for the global aviation industry, is using DS's CATIA Composites Design to develop aircraft parts. Composites are ultra lightweight and can be formed into any shape, allowing for inventive industrial design and giving Chengdu the means to beat 21st century aviation challenges and a strong competitive edge.

For today's airline companies, increasing oil prices, driven by international political tensions, make for steeper operational costs and require firms to charge more. Add to that the growing pressure to keep things "green," like reducing noise pollution and harmful gas emissions. Developing a competitive edge has never been so crucial, and innovation- thanks to composites- is essential to surmounting difficulties. Chengdu Aircraft is expanding its activities to cover the entire composites design process and provide customers with breakthrough design and manufacturing solutions.

"CATIA Composites Design has enabled us to shorten our manufacturing design cycle time by 50%, which is key for us to meet the tight deadlines of our OEM partners and focus more resources on innovation," says Youyi Wen, director of composites department, Chengdu Aircraft Industrial Group. "CATIA Composites Design is fundamental to our success and makes working with composites, which requires new software, new machines- a whole new way of working, much easier."

"DS is delighted to be working with Chengdu on this revolutionary technology. CATIA Composites Design provides a collaborative environment that covers the entire composites process. Engineers can focus on creating optimal designs to fully exploit composites' advantages," says Denis Georgeon, general manager PLM Channel China & South Asia, Dassault Systèmes. An important strength of CATIA Composites Design stems from its synchronization mechanisms, which allow engineers- no matter their location- to work simultaneously on the same 3D design. And thanks to DS's strategic software and industrial partnerships, CATIA Composites Design seamlessly communicates to composite-specific production equipment, enabling Chengdu to industrialize.

Capitalizing on its composites know-how, Chengdu is launching a Composites Manufacturing Research Center in partnership with Dassault Systèmes that will be dedicated to investigating alternative manufacturing technologies.

**About Chengdu Aircraft Industrial Group**

Chengdu Aircraft Industrial (Group) Co. Ltd of China Aviation Industry Corporation I was founded in 1958 and is an important base for the design, development and batch manufacturing of fighter planes in China. It also is a leading developer of civilian aircraft and other industrial products in the Chinese aerospace industry.

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### *Dartmouth Engineering Researchers Use PTC Pro/ENGINEER® Solutions to Create Affordable Robots*

26 March 2007

PTC announced that researchers at the Thayer School of Engineering at Dartmouth are using Pro/ENGINEER, including Pro/ENGINEER Mechanica®, to develop autonomous, mobile, high-speed, low-cost robots as part of their study of cooperative control. These robots can be used to assist community first responders in assessing potentially dangerous situations rapidly and safely, with reduced risks to the responders. Pro/ENGINEER is used by forty-five of the top fifty-two engineering universities in the United States.

The Dartmouth engineering research team is studying the concept of cooperative control which allows one person to control multiple high-speed, all terrain robots. This approach eliminates the need for the one soldier per robot control procedure currently required with highly specialized military use robots. As a result, costs can be dramatically reduced enabling resource constrained communities to leverage robotics technology to optimize their public safety initiatives. These all-terrain robots are also being used as “scout” vehicles to characterize terrain and reduce the potential for robot immobilization.

Unable to locate commercially available robots for use in the study, the researchers opted to develop their own robots. Using the advanced capabilities of Pro/ENGINEER, the chassis was designed in less than twelve months at a fraction of the costs. Pro/ENGINEER Mechanica was utilized to perform structural analysis to ensure maneuverability on various terrains before creating the prototype. Furthermore, the researchers were able to use the 3D models to determine the optimum control and terrain algorithms for the robot, saving the time and costs of iterative prototyping.

“Robotics development is highly complex, involving mechanical, electrical and software components. As a result, it is typically a very long and costly process,” says Laura R. Ray, associate professor of engineering at Dartmouth. “The 3D solid modeling capabilities of Pro/ENGINEER allowed us to determine the final outcome before investing time and money in the prototype. We could be fully confident that all the parts were going to fit, minimizing the impact of rework.”

"The Dartmouth research project is an excellent example of how educational institutions can use PTC's leading technology solutions to prepare their students to compete effectively in the workforce," says John Stuart, senior vice president, global partners and education, PTC. "The student researchers at Dartmouth will have the added experience of using their engineering skills to create an innovative robot that can help solve the real world problem of public safety."

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### *Delcam's ArtCAM Helps Provide Houses for Homeless Birds*

27 March 2007

Randy Martin, the owner and chief designer of Blue Moon Designs, always enjoyed amateur woodwork so, after many years on the road as a salesman, he decided to start a company using CNC machines to carve decorative bird houses. The challenge was to make sure they were well finished, individual items but also that they were produced in an efficient manner. Using Delcam's ArtCAM Pro software helped Mr. Martin to meet that challenge.

Firstly, Mr. Martin converted a Scolpitrice carving machine to be CNC controlled and so solved the problem of carving low-volume parts in mini-production runs. The machine has 16 spindles, which can cut the same part simultaneously. He has some other customised machines as well, giving a total capacity of 26 spindles and up to 65 cut parts per shift.

The next problem was creating the models and toolpaths he needed to cut them. Mr. Martin struggled until he saw ArtCAM Pro at a local woodworker's trade show. "I realised immediately that it was much more suitable and easier to use than my previous software," he explained.

With ArtCAM Pro, Mr. Martin now uses a combination of approaches to develop his designs. Typically, he sketches the idea for a new design and scans the image into ArtCAM Pro. He also uses a library of component pieces taken from existing designs, as well as parts created completely within the software.

Mr. Martin commented, "With ArtCAM Pro, I can create the models at a fraction of the cost and in much less time. The software allows me to edit and modify the designs just the way I want."

Once the model has been perfected, he uses the flexible machining strategies in ArtCAM Pro to create the toolpaths. Cutting small production runs means it is essential to generate an efficient toolpath and to get an excellent finished product. Parts are cut in batches and then stored until someone orders that design; they are then assembled and finished to the customers' requirements.

As well as the production side of the business, Mr. Martin enjoys the custom work that he can also complete with his software. "Recently, we were able to carve a restoration component for a 150-year-old piece of furniture," he said. "By scanning the original part, it was easy to repair the model in ArtCAM Pro and then carve an accurate replacement."

The custom side of the business is something that Mr. Martin would like to develop more over the coming years and he is also looking to expand into other areas. "We are hoping to develop a range of designs for other products," he commented. "We're also now offering the service to carve parts for other companies who may need to make multiple copies but do not have our capacity for production."

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### *European Communication Service Extends Agreement with Telelogic Worth 748,345 EUR*

30 March 2007

Telelogic announced an agreement extension for Telelogic Solutions for Enterprise Lifecycle Management (ELM) with a leading European telecommunications service provider. The 3.5 year license and maintenance deal is worth 748,345 EUR.

The deal will see the company, which has already standardized on Telelogic DOORS®, Telelogic Tau® and Telelogic System Architect® to provide their enterprise-level capability for requirements management and modeling in their IT organization, standardize on Telelogic Synergy™ for change and configuration management to the enterprise agreement. Both of the company's investment decisions support their IT department's strategic process improvement initiatives.

"The company required a truly integrated enterprise solution, one that improves both the business and development processes," said Anders Lidbeck, CEO and President of Telelogic. "Our ability to deliver against the company's initial stringent process improvement requirements ensured Telelogic was the first choice for their change and configuration management needs."

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### *Glotman-Simpson Wins Revit BIM Experience Award for Furthering Creative and Collaborative Efforts with Revit BIM Platform*

30 March 2007

Autodesk, Inc. announced that it has presented a Revit BIM Experience Award to Glotman-Simpson for its use of Revit Structure building information modeling (BIM) software for structural engineers. Glotman-Simpson uses Revit Structure to collaborate with architects using Revit Architecture software to improve productivity and efficiency. The Revit BIM Experience Award is presented to firms for their innovation and excellence in implementing the Revit platform for BIM to create quality, complex designs and collaborate across the building design disciplines.

"Using Revit Structure gives us a strategic, competitive advantage over other firms. Using this solution we are able to ensure complete, accurate designs, all the while providing our clients with a high level of service," said Geoffrey Glotman, Managing Principal for Glotman-Simpson. "We're able to provide information to clients directly from the model and quickly respond to any requests for design changes. As a result, our clients can make informed decisions, faster."

Based in Vancouver, British Columbia, Canada, Glotman-Simpson delivers structural engineering consulting services throughout Canada and in the United States. The firm has won numerous awards and

completed more than 4,000 residential, commercial, industrial and institutional projects. Glotman-Simpson's commitment to leading-edge technology led to the firm's adoption of Revit Structure in 2005, and since that time Glotman-Simpson has undertaken numerous projects using the software.

One of those projects is the Grigio development in the heart of San Diego, Calif. A 43-story, 1.2 million square-foot mix of hotel, condominium, and rental units, the Grigio project will contain more residences than any other building in San Diego. Adding to the complexity of the Grigio development is the project site, which has a drastic slope causing conditions at grade to vary greatly across five floors. The size and scope of this large project required close coordination between Glotman-Simpson and the lead architect on the project, KMA Architecture & Engineering, who used Revit Architecture for the building design. Using the Revit platform for this complex project, the firms were able to coordinate many of the project's intricate elements in a single building information model.

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### *Machinist Gets a CAD Education the Easy Way*

26 March 2007

Canadian machinist Westley Chagnon was very familiar with reading technical drawings. For the last 35 years, he performed his trade at Crown Packaging, a Calgary can manufacturer, where he manually machined dies at extremely low tolerances. Early in his career, he worked from old hand-drawn blueprints, and in the last decade, he received his specs on CAD printouts. He had no idea, however, how to create these drawings until he began to explore the new digital world of fabrication on his own. After some early frustration in becoming CAD proficient, Chagnon finally found the path of least resistance from software and support from Alibre, Inc. Now he gets paid to make technical drawings.

Steeped in the traditions of manual milling, Chagnon at first was intimidated by the digital tools when he bought his own CNC spindle and lathe and all the related software.

"For years I wanted to learn CAD. Every time I talked to somebody about it, they made it seem like rocket science. I thought I needed to get organized about it." In May of 2006, Chagnon made a concerted effort to learn the raw machine language of CNC, g-code, along with the essentials of computerized drafting.

"I tried out several sample programs of CAD packages. I went through two of them, printing out 500 pages of manuals, but I couldn't make heads or tails of it. I thought 'what a trip in futility this was going to be.' I had bought these machines, and now I can't run them." For a while, Chagnon set aside his CAD frustration and ran his mill through a g-code controller, which permitted him to cut basic shapes through simple programming. "I thought maybe I don't have to learn CAD that bad, because I can tell my machine to go up two inches and over one inch, and so forth."

But once he wanted to do more complex parts, he realized the need for drawn schematics. "One day I had to do a part that had a contour -- one radius blending into another. I went to friends who knew g-code to try and write it, but the bottom line was that I needed to know the points of intersection. That's when I picked up Alibre Design."

To chart out the geometry of his design problem, Chagnon turned to another sample software he had not yet tried, Alibre Design Xpress. The free download has nearly all the parametric modeling capabilities needed to build, print, or export small assemblies.

"It was a simple question: 'How do I draw two circles?'" recalls Chagnon. "I called tech support, and Alibre was willing to help me. They showed me a lot of 'how-to' examples within the program. I thought that's pretty great, since I'm using a free piece of software."

After technicians at Alibre showed how easy it was to model the shapes he needed, Chagnon committed fully to the application. He purchased the full version of Alibre Design and extra tutorial DVDs. "Their manuals and their training videos are excellent. I started to catch on."

Only a few weeks later, Chagnon was talking with an old friend, Keith Campbell, owner and president of Select Energy Systems, a Calgary manufacturing firm that specializes in coiled tubing for natural gas extraction. Campbell explained that his engineering department was overloaded with projects and he needed technical drawings of a new design. Chagnon offered to help. Campbell drew him rough sketches of the mechanics he needed - a complete coiled tubing hanging system that would lock the piping in place as it attached a conventional natural gas well.

The next morning, Chagnon dropped off a full set of 2D drawings after modeling the assembly in Alibre Design the night before. Campbell was not even expecting results so soon. "I was impressed with the design and the timeline he got it done in, considering he was still learning the program," says Campbell. "The drawings were pretty much perfect. Everything was machined to those drawings and everything fit together. It worked out extremely well."

Campbell continues to outsource drawing work to Chagnon. In just a short time, a hobbyist who "couldn't so much as draw a line on a computer" was able to create professional-grade drawings ready for shop fabrication. Chagnon credits his ability to so quickly excel in the technology to Alibre Design's straightforward approach to modeling, as well as the generous assistance and instruction from the software maker.

"If I was to look for any downfalls to this software, I can't find any," remarks Chagnon. "The support that comes with Alibre is impeccable. Sometimes I feel like calling the guys up in support just to say, 'hi how it going, guys? I don't have a complaint. I don't have a problem. I just want to say thanks for helping me when I needed it,' because it was nothing for them to spend an hour on the phone with me."

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### *Renesas Technology Chooses Synopsys IC Compiler Solution for SoC Design Flow*

27 March 2007

Synopsys, Inc. announced that Renesas Technology Corp. has adopted Synopsys' IC Compiler next-generation place-and-route solution for its production IC design flow. The growing complexity of

Renesas' designs required them to meet timing in several different functional modes. After thoroughly evaluating all available options, Renesas selected Synopsys' IC Compiler solution for its ability to achieve desired chip performance by concurrently optimizing all timing modes through its true multi-mode capability. Renesas also reaped the benefits of significantly faster turnaround time and enhanced ease-of-use.

"Having our chips work at high speed across many different functional modes has been a growing challenge for us, even with mainstream consumer designs," said Teruaki Harada, department manager, DFM & EDA Technology Development Dept. at Design Technology Div. at Renesas Technology Corp. "We have relied on Synopsys tools to help us with our many challenging designs and now, with the IC Compiler solution, we have addressed the very pressing issue of multi-mode timing."

Renesas evaluated all available multi-mode approaches, including sequential and merging techniques, using a demanding set of 15 test cases which included a large 0.13-micron consumer design with more than 3.5-million gates and 5 operating modes. Renesas found that the IC Compiler solution satisfied all requirements and delivered desired performance for multi-mode optimization. The IC Compiler physical implementation solution relies on Extended Physical Synthesis (XPS) technology to increase optimization efficiency, which not only offered Renesas improved clock speed results, but also enabled the designers to reduce the total cell area of the design. XPS is a new architecture that combines synthesis, placement, clock and routing into a unified optimization environment. As a result, Renesas found the IC Compiler solution to be faster and significantly easier to use than alternate solutions, even for single-mode designs.

"Renesas has a long history of working closely with Synopsys on their most challenging designs," said Antun Domic, senior vice president and general manager of Synopsys' Implementation Group. "By selecting our IC Compiler solution for its true concurrent multi-mode optimization capability, Renesas can now reduce design time while increasing performance."

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### *SawStop Makes Woodworking Safer With Finger-Saving Table Saw Designed in SolidWorks and COSMOS*

27 March 2007

A small Oregon company is changing woodworking professionals' jobs with a table saw designed in SolidWorks® software that only cuts wood – not fingers. SawStop has invented a table saw that immediately retracts the blade when it touches a finger, making woodworking safer and eliminating painful and very costly medical procedures.

Table saws are involved in more than 60,000 accidents every year – or one accident every nine minutes –– according to the U.S. Consumer Product Safety Commission. Those accidents result in nearly $2 billion of injury-related costs annually. Realizing the need for a safer saw, lifelong woodworker Steve Gass applied his doctorate in physics to design a saw that runs with a small electrical current on the blade. When the blade touches a finger (or something else that conducts electrical current), the current

drops and engages a brake. As the blade's teeth sink into the brake, the momentum forces the blade to drop below the table. The entire process takes only three milliseconds, which is a fraction of the time it takes to blink your eye.

SawStop Vice President of Engineering Dave Fulmer said inventing the product went more smoothly than learning to use the first CAD software the company bought. "We're all inventors or engineers, but none of us really had any CAD experience," he said. "It took us about eight months to realize that purchasing Autodesk Inventor® was a mistake. It wasn't very intuitive, it didn't handle complex assemblies very well, and all of our manufacturers in Taiwan used SolidWorks. In just a couple of weeks learning SolidWorks, we were able to design complex components such as the brake mechanism, including the spring that sets the brake into the blade to stop the saw."

Fulmer and his team rely on COSMOSXpress™ and COSMOSWorks® Designer analysis software to ensure the table saws perform as expected and can stand up to constant use. SolidWorks' integration with these products enables SawStop to minimize prototyping costs and time and eliminate added manufacturing costs from overbuilding.

SolidWorks CEO John McEleney recently demonstrated how the saw works using a hot dog in front of more than 3,000 attendees at SolidWorks World 2007. "The speed with which the blade retracts and the sound it makes is stunning," he said. "So far, this invention has prevented nearly 150 serious injuries, and that number will increase as sales continue to grow. SawStop is another example of a small company with a groundbreaking idea designing great products that make a difference."

SawStop relies on authorized SolidWorks reseller Shounco Design Studios for ongoing software training, implementation, and support. To see how the SawStop can save woodworkers' fingers, watch it in action at http://www.sawstop.com/media/Table%20Saw%20-%20WMV%20high.wmv.

**About Shounco Design Studios**

Shounco Design Studios, Inc. is a Northwest CAE /CAD/ CAM company serving Oregon and Washington since 1995. Visit the company's Web site at http://www.shounco.com/.

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### *Schaeffler Optimizes Roller Bearing Designs With LMS Durability Solutions*

28 March 2007

LMS announced that the Schaeffler Group has implemented LMS TecWare to accelerate its durability testing process, often completing cycles in a few days instead of the several weeks or months. In addition, advanced analysis routines in the LMS software more precisely determine the fatigue life of products, enabling Schaeffler engineers to develop designs that closely match expected operating load conditions.

Based in Germany, Schaeffler manufacturers INA and FAG brands of high-quality bearings and other critical components for automotive, aerospace and other industries worldwide. For over 50 years, Schaeffler components and systems have ensured that vehicles achieve higher technical precision, are safer and provide longer service life. This is attained by constantly analyzing existing solutions, forging new ideas, and developing products that are better than those of the past. The company utilizes LMS software to streamline durability testing of its broad range of products, which is among the most comprehensive in the roller bearing industry and includes volume-produced catalog parts as well as custom-designed specialty components.

LMS TecWare accelerates laboratory tests with advanced durability load data processing algorithms that import, correlate and analyze large amounts of test data from multiple sources to identify key fatigue load profiles encountered by the part during operation. The software then determines compressed load time histories that deliver this same damage potential, defines an accelerated test routine based on these repetitive load signals and automates the workflow process from start to finish.

“Using LMS TecWare, we can duplicate years of key fatigue cycles typically in just a few days of testing,” says Dr. Rüdinger Dupke, Durability and Load Data Analysis Group Manager at Schaeffler. “Because operating loads are precisely identified by the system, our engineers can better develop parts with adequate fatigue life without being over-designed, allowing us to minimize product size, weight and cost.”

Filip Pintelon, Vice President and General Manager of the LMS Test Division, commented, “We are very pleased with Schaeffler’s choice for the LMS TecWare solution. With today’s increasing pressure for higher quality and shorter time to market, the LMS TecWare solution allows engineers to optimize product durability while significantly compressing test cycles. We are confident that LMS TecWare will deliver a valuable contribution to the solid reputation of Schaeffler to bring innovative and reliable products to market.”

For more information on LMS TecWare, please visit http://www.lmsintl.com/testlab/durability-testing

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### *Synopsys Enables STMicroelectronics to Achieve First-Silicon Success for 65-nm Dual High-Definition MPEG-4 Decoder*

27 March 2007

Synopsys, Inc. announced that it has enabled STMicroelectronics to achieve first-silicon success for its new STi7200 dual-video-stream high-definition (HD) decoder, aiming to serve a broad range of digital consumer applications including set-top boxes, high-definition DVDs (dual-standard Blu-ray and HD-DVD) and digital TVs. Synopsys collaborated with STMicroelectronics on this highly integrated system-on-chip (SoC) throughout the flow and delivered a comprehensive solution including implementation, verification, intellectual property (IP) cores and services. At 25 million synthesized gates, the STi7200 is the first device of its kind manufactured using 65-nanometer (nm) technology and is a major step forward in providing full high-definition picture quality in a variety of affordable consumer devices.

"I am impressed by the strength of Synopsys' comprehensive technology portfolio and by the outstanding responsiveness and dedication of the Synopsys service and support organizations, who have truly become members of our design team," said Thierry Bauchon, R&D director, Home Entertainment & Displays Group, STMicroelectronics. "Synopsys helped us throughout the entire flow, and the combination of their technology leadership, high-quality IP and best-in-class service and support was instrumental in STMicroelectronics achieving first-silicon success for the STi7200 device."

At the system level, STMicroelectronics used the Synopsys coreAssembler™ SPIRIT-based IP assembly flow—based on the SPIRIT Consortium's IP-XACT™ format—to rapidly configure and assemble Synopsys DesignWare® IP cores—including a PCI Express® Root Complex, USB 2.0 Host and SATA Host—and dozens of proprietary IP blocks, which had been pre-packaged with the help of Synopsys Professional Services consultants. STMicroelectronics achieved a 40 percent reduction in the time to perform top-level capture functions and integrate more than 40 pieces of IP and 30 custom register transfer level (RTL) blocks.

For functional verification, STMicroelectronics used the Synopsys VCS® verification solution with SystemVerilog native testbench and the VMM methodology, which enabled a 15X reduction in turnaround time over previous approaches for the validation of the on-chip bus after an RTL modification. STMicroelectronics also took advantage of the VCS solution's built-in support for SystemC simulation and debug of behavioral models.

At the implementation level, STMicroelectronics widely utilized the Synopsys Design Compiler synthesis solution, DFT MAX test compression and Formality® equivalence checking to manage the challenging size and aggressive performance targets of this highly complex decoder in a very short time. STMicroelectronics also utilized Synopsys' IC Compiler for placement and routing of one block of the STi7200, which accounted for almost one million synthesized instances in this device.

Synopsys' Hercules® Physical Verification Suite, Star-RCXT™ extraction and PrimeRail power network analysis solutions helped to significantly reduce turnaround time for assessing the power and ground network integrity by identifying and enabling the correction of a number of weaknesses without negatively impacting the tight tapeout schedule. This achievement is especially important given the complexity of the STi7200 chip.

"Synopsys has been attentively listening to STMicroelectronics' design community and broadening the scope of our ongoing collaboration to encompass the complete flow," said John Chilton, Synopsys senior vice president of Marketing and Business Development. "Having such a highly complex device achieve first-pass silicon success is a tremendous engineering achievement and further evidence of the value Synopsys' complete solution can provide our customers. Our unique combination of comprehensive implementation, verification and system-level solutions, proven IP cores and world-class services enables us to help our customers solve their toughest challenges and achieve predictable success."

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### *Telelogic Signs 580,000 USD Agreement with World Leading Automotive Manufacturer*

27 March

Telelogic an agreement with a leading automotive manufacturer worth 580,000 USD. The agreement includes licenses and maintenance for Telelogic DOORS® for requirements management, analysis and definition.

The customer has standardized on DOORS as part of their global process improvement initiative. Selecting Telelogic as the only provider capable of delivering against their rigorous criteria including requirements for bi-directional traceability and reuse.

“The customer wants to improve quality and the time to market for their important new vehicles over the next five years period”. said Anders Lidbeck, President and CEO of Telelogic. ”Through Telelogic’s industry leadership and best in class solution we were able to seal the deal”.

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### *Telelogic Signs 865,000 Euro Contract with Rail Signaling Systems Supplier*

30 March 2007

Telelogic announced that it has signed a five year license and maintenance contract worth 865,000 EUR with a leading provider of rail signaling technology.

The company already using key components of Telelogic’s solutions for Enterprise Lifecycle Management (ELM); Telelogic DOORS® for requirements management, definition and analysis, Telelogic Synergy™ for change and configuration management and Telelogic Tau® for advanced systems and software development, within the R&D and key development projects will extend the usage across additional development teams.

“By taking advantage of Telelogic’s solutions for ELM, customers improve quality, while significantly reducing time-to-market and overall costs," said Anders Lidbeck, President and CEO of Telelogic. "The decision to extend and expand the current agreement demonstrates confidence in Telelogic’s approach and the value we offer our customers."

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### *Ubicom Selects Cadence Encounter Timing System For Timing And Signal Integrity Signoff*

27 March 2007

Cadence Design Systems, Inc. announced that Ubicom, a leading developer of communications and media processors and related software platforms, has incorporated the Cadence® Encounter® Timing System into its overall design flow. The Encounter Timing System has allowed Ubicom to streamline the

overall time needed to verify their most advanced designs, enhancing the ability to deliver interactive applications and multimedia content for the digital home.

The Encounter Timing System is the most complete and integrated static timing analysis (STA) environment for faster optimization and signoff verification. With the Encounter Timing System, designers of increasingly complex integrated circuits may gain improved time to market, achieve better productivity, signoff-quality timing and signal-integrity analysis. The same signoff-quality analysis is also integrated within the Cadence SoC Encounter™ RTL-to-GDSII system for digital implementation processes.

The Encounter Timing System was selected by Ubicom for its ability to provide a consistent view of timing throughout the design flow while accounting for crosstalk, IR drop, electromigration, and thermal and systematic manufacturing variability effects. To get a true sense of timing, design tools must concurrently account for these interdependent effects during physical implementation, not waiting until the later stages of the design flow.

"Today's nanometer designs face severe technological challenges caused by increasing design size and performance, as well as process complexities," said Jon Gibbons, vice president of Engineering at Ubicom. "It was important for us to have a signoff solution for our ASIC flow that would accurately address the inter-dependencies of signal integrity, power, and timing. We were impressed that the Encounter Timing System brought all this together in a single solution and will fit seamlessly into our existing flow. Given all alternatives in the market, we believe the Encounter Timing System is the best and most complete signoff solution."

"The Encounter Timing System clearly answers the unmet needs for a complete signoff analysis and the direct integration within design implementation process for nanometer design closure," said Dr. Chi-Ping Hsu, corporate vice president, IC Digital and Power Forward at Cadence. "It offers customers the utmost in signoff accuracy, performance, and productivity for today's most complex designs, which is why it is being embraced by foundries, ASIC providers, and leading fabless semiconductor companies."

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### *Winbond Israel Advances New Product Innovation with Sopheon's Accolade® ;Semiconductor Maker Strengthens Innovation Processes and Enhances Team Collaboration with Product Life Cycle Management System*

27 March 2007

Sopheon announced that Winbond Israel Ltd., a developer of semiconductor integrated circuits and software, is implementing Sopheon's Accolade system to support the automation and management of its innovation processes. The product life cycle management solution is being deployed in the organization's Israeli research and development centers.

Winbond Israel is a subsidiary of Taiwan-based Winbond Electronics Corporation, one of the world's leading producers of semiconductor solutions. The Israeli operation specializes in developing and marketing products for personal computers, including Super I/O embedded controllers and security devices. In recent years, the semiconductor industry as a whole has continued to grow, but the rate of expansion has slowed. This trend, combined with the emergence of nontraditional applications in such areas as Trusted Platform Modules and SideShow™ controllers, has heightened the need for both process and product innovation.

Winbond Israel's implementation of Accolade is central to the organization's strategy for enhancing its innovation process and increasing the business return on investments in new products. The system will be used to collect and manage new product ideas, and to enable online collaboration among project teams working on product concepts selected for development. Executives, process owners and team members will benefit from on-demand desktop access to a central repository of the data needed to review and assess the status and value of projects in the developmental pipeline. At the same time, Accolade's resource planning capabilities will help ensure that team efforts are properly aligned to support successful completion of priority project work.

"One of the primary reasons we chose Sopheon as a solution provider is their domain expertise," said Yoram Avigdor, program management officer and security product manager at Winbond Israel. "Their support helped to ensure that the innovation processes we put in place are grounded in the latest best practices. Accolade's ease-of-use and simple configurability were also important. But what ultimately sold us on Sopheon's system was the fact that it matches up well with our culture. Winbond's business creed is to deliver what we commit. Accolade's capabilities are a glove-fit with the emphasis on innovation, teamwork and accountability upon which that creed is built."

"In the semiconductor industry, a supplier's capacity to respond quickly to custom, end-user requirements is essential to business success," said Nigel Cordery, European director for Sopheon. "Accolade not only gives Winbond an automated best-practice process structure, it provides them with the kind of strategic oversight and agility needed to quickly deliver solutions that customers will value."

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### *WorkNC is the Route for Rapid Manufacture at Eurocopter*

26 March 2007

Eurocopter can trace its roots back 100 years to some of the earliest experiments in helicopter flight. It operates from six locations across Europe and has achieved a turnover in 2006 of 4.9 billion Euros, an increase of 40% from 2005. The Group produces a range of civil and military helicopters, and it has achieved a 52% market share in the private, corporate, and public service sectors. Worldwide, it has around 2,500 customers in 139 different countries, and has sold approximately 9,500 aircraft. "We have a duty to fulfill for each customer and our overriding aim is their satisfaction," explains Christophe Celor from the Corporate Communication & Information Department. "Customization is an increasing requirement, so we have had to organize ourselves accordingly."

To meet these demands, the company has established four Industrial Skills Centers. Each Center operates autonomously as a business unit but maintains links to the Central Engineering Department. The objective of each Center is to design, manufacture and industrialize its products, which are destined for Eurocopter's civil and government sector helicopter assembly lines. Additionally, it provides customer support and administers its own planning and purchasing policies.

The Structure Industrial Skills Center initially produced batches of finished parts. However, a change in policy resulted in these being outsourced and the Center now concentrates on the manufacture of prototype parts; making customized non standard parts; helicopter development; and productionizing components ready for batch manufacture. The Rapid Manufacturing Department, formed to meet these new objectives, capitalized on the existing skills within Eurocopter, providing faster response to the requirements of its customers, and new concepts in the manufacture of metal and composite structural parts. The five-man team produces 65% of the molds for composite parts, 30% of the sheet metal dies and 5% of the prototype parts for the Research and Development Department. Its top priority is rapid turnaround.

To achieve its goals the Center needed to find a method which would enable it to rapidly manufacture molds for composite parts, and sheet metal dies for prototype and low volume components. Michel Labarthe, Manager of the Structure Industrial Skills Center said, "Due to the increased customization applied to our range of products, we had to implement resources adapted to this new requirement." In 2002 the company carried out a feasibility study, benchmarking different CAM systems and CNC machines. In particular, it was looking for a close link between the software and the machine tool; a reliable toolpath with clear collision control and display capabilities; an extensive tool library; an ergonomic and easy to use interface; and a means of reducing design times.

Extensive production tests led Eurocopter to choose WorkNC, WorkNC-CAD and a TNB CNC machine tool. Michel Labarthe said, "We reduced the time for machining a shroud from 32 hours to 4 hours 5 minutes. The figures speak for themselves. We also greatly appreciated the depth of collaboration between the machine tool manufacturer and Sescoi. During the testing period, for example, the predicted times really were the times which we achieved. This wasn't always the case for the other systems that we tested."

Eurocopter's design and modeling is completed in CATIA V4 and V5. WorkNC-CAD is used to interpret these designs and prepare the models for machining in WorkNC. Here the software automatically calculates the geometry, generates reliable toolpaths and simulates the machining. Within three weeks of the installation of WorkNC and the TNB machine tool, the company was producing its first tools. Michel Labarthe added, "Our main concern is always the same - to reduce part manufacturing lead times. This is very important to us as an assembly line stoppage is very expensive." He is delighted with the performance of WorkNC and the TNB machine. " We have achieved our objectives, halving production times on our sheet metal parts, including both the programming and machining phases."

2006 saw investment in an additional WorkNC and WorkNC-CAD system with a direct CATIA interface, together with a second TNB machine. Michel Labarthe concluded, "Our four operators work three, eight hour shifts per day. Additionally, we have implemented alert indicator methodology to enable us to monitor jobs securely and easily." With the additional equipment, the Industrial Skills Center has

achieved its rapid manufacturing target, and is now able to supply its customers with mass produced and customized parts within 15 days.

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# Product News

### *Adobe Unveils Preview of Acrobat 3D Version 8*

29 March 2007

Adobe Systems Incorporated announced a public preview of Adobe® Acrobat® 3D Version 8 software, a major upgrade to the desktop application for driving PDF document-based 3D design collaboration and computer-aided design (CAD) data interoperability capabilities to virtually anyone across the extended enterprise. Starting immediately, users worldwide can download a beta version of the product free from Adobe Labs, and experience the new and enhanced capabilities it will deliver for professionals in the manufacturing and architecture, engineering and construction (AEC) industries. The preview can be downloaded at labs.adobe.com/technologies/acrobat3d_version8/

"Acrobat 3D and PDF have gained considerable traction in manufacturing and AEC over the past year as a means for driving 3D-based communication and collaboration processes leveraging a ubiquitous, trusted file format," said Tom Hale, senior vice president, Knowledge Worker Business Unit at Adobe. "Today, we're excited to provide users around the world free access to a beta of Acrobat 3D Version 8. We encourage anyone with interest in 3D to experience the dramatic advances we've made in terms of file compression, precision and CAD data interoperability. We look forward to hearing the thoughts and first-hand experiences of users throughout the preview period."

With Acrobat 3D Version 8, design engineering, technical publishing and creative professionals in manufacturing industries such as automotive, aerospace and heavy machinery, as well as the AEC market, can convert virtually any 3D CAD file and other critical project data into a highly compressed PDF document with precise geometry. The PDF file can then be shared with colleagues, suppliers, partners, and customers for more secure visualization, collaboration and CAD data interoperability in an archival-quality format.

Once 3D models are in PDF, Acrobat 3D Version 8 users can enable extended teams to participate in an efficient document review process leveraging the free, ubiquitous Adobe Reader® software. Adobe Reader users can view detailed product structure and, when enabled by Acrobat 3D Version 8, have the ability to use commenting, measurement and cross-section tools directly on 3D objects in PDF files1.

Acrobat 3D Version 8 will deliver enhanced capabilities for producing compressed PDF documents with precise geometry from large, complex CAD assemblies. The product supports conversion to 3D PDF from over 40 formats, including those for Autodesk Inventor, Dassault Systemes CATIA, PTC Pro/ENGINEER, SolidWorks, and UGS NX and I-deas. The latest version also will enable users to distribute product manufacturing information—used to convey geometric dimensioning and tolerancing,

annotations, and dimensions directly on a 3D model—in PDF. In addition, Acrobat 3D Version 8 users will have the option of exporting precise manufacturing CAD data from PDF into neutral file formats such as STEP, IGES and Parasolid for downstream processes such as machining operations and tool and mold design.

Adobe Reader and Adobe Flash® Player, the company's cross-platform client technologies, are installed on over 700 million connected PCs and devices worldwide.

**Pricing and Availability**

The free, fully functional beta version of Acrobat 3D Version 8 is immediately available in English, French and German language versions at labs.adobe.com/technologies/acrobat3d_version8/. The preview is available for Microsoft® Windows® 2000 with Service Pack 4, Windows XP Professional, Home or Tablet PC Editions with Service Pack 2, and Windows Vista™ Ultimate, Enterprise, Business, Home Premium, or Home Basic Editions. The beta version will cease operating on June 15, 2007. Feedback can be submitted and discussed on the Adobe Labs forum. Technical support is not available during the preview period.

Acrobat 3D Version 8 is expected to ship in spring 2007. The product is expected to be available for an estimated street price of US$9952. Registered users who purchase Acrobat 3D from Sept. 18, 2006 until the ship of Acrobat 3D Version 8 will be eligible to receive a free upgrade to Acrobat 3D Version 83.

More information on Acrobat 3D Version 8 is available at http://www.adobe.com/go/acrobat3dv8.

1. Requires Adobe Reader 7.0.7 or later.

2. Sales tax, shipping and handling may apply. Reseller prices may vary.

3. Sales tax, shipping and handling may apply.

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### *ASCON Released Template Manager - New Application for KOMPAS-3D*

27 March 2007

ASCON announced the availability of new add-on for its 3D Parametric Modelling Solution – KOMPAS-3D. New application, called Template Manager, intended for creating, maintaining and use of customized template libraries when working in KOMPAS-3D.

The application will allow KOMPAS users to create a wide range of KOMPAS-3D thematic libraries and fill them with necessary for working objects (templates).

User can set to Template the variables from connected MS Excel table when pasted template to KOMPAS-3D document. A template can be pasted to KOMPAS-3D document as a set of objects (lines, arcs, curves etc.); as a library macro element or component which can be edited with Template Manager tools; as a part or an assembly, which can be edited with KOMPAS-3D tools; and others.

The Template library can be completed by users' details, fragments and parametric tables, linked to each other. One MS Excel document may correspond to several parts or fragment files from Template Library.

Template Manager requires Microsoft Excel or OpenOffice.org Calc installed.

About KOMPAS-3D. KOMPAS-3D, the Mechanical CAD solution from ASCON provides effective industrial product development, release of design and drafting documentation. KOMPAS-3D combines all basic features for Parametric 3D Solid Modelling, full-scale 2D Design and Drafting opportunities, special add-ons for photo rendering, motion simulation, kinematic and dynamic analysis. KOMPAS solutions are famous for its powerful functionality in the mid-range CAD segment, easy-to-use and learn features and comfortable interface, reasonable price and strong compatibility functions. During over 17 years history of KOMPAS software solutions it has subscribed about 3000 corporate customers with over 30 000 seats installed.

ASCON: http://www.ascon.ru/english

For additional information, please, contact Your nearest VAR or ASCON Headquarter at contact@ascon.ru or +7 812 703-39-33.

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### *AVEVA and INOVx Announce Technology Integration Alliance*

28 March 2007

AVEVA and INOVx Solutions, Inc. announced an alliance to integrate laser scanning technology and plant design software capabilities. INOVx's RealityLINx Exchange product is being integrated with AVEVA PDMS using AVEVA Laser Model Interface.

Recent advances in laser scan technology have made the use of laser scan point cloud data much more viable in the plant industries. Engineering project teams benefit very substantially from close interoperation of laser scan data with 3D CAD plant design systems like PDMS. This partnership provides a cost-effective integrated solution with the potential to reduce plant downtime on revamp and retrofit projects by combining the power of RealityLINx with the global reach of AVEVA PDMS.

RealityLINx Exchange incorporates new functionality for rendering laser scan point cloud data in 3D CAD environments. INOVx PlantLINx and RealityLINx software provide best-in-class capability for modelling from laser scan point clouds and subsequently providing Virtualization™ for industrial operations and maintenance.

"INOVx has long been a leader in the application of laser scanning technology. We are happy to extend RealityLINx point cloud functionality to work with the leading 3D design modelling software from AVEVA", said Costantino Lanza, CEO of INOVx. "The AVEVA Laser Model Interface provides a perfect fit to make sure our products dovetail together."

"AVEVA's as-built strategy provides open access to laser scan point cloud data in PDMS, irrespective of the laser scan technology used in the plant survey. This partnership recognizes INOVx as one of the leading laser scanning solution providers in the market today. We are very pleased to be coupling our products together for the mutual benefit of our customers" said Richard Longdon, CEO of AVEVA.

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### *Cadence Global Route Environment Technology Sets New Standards For PCB Design*

26 March 2007

Cadence Design Systems, Inc. announced the Global Route Environment technology for Cadence® Allegro® PCB design. This technology combines a graphical interconnect flow-planning architecture and a hierarchically-aware global routing engine to provide PCB designers with an automated, intelligent planning and routing environment. As the first solution of its kind to bring intelligent automation where no automation was previously available, Global Route Environment technology represents a significant leap forward and establishes a new PCB design paradigm.

Prior to this technology, PCB designers spent weeks or months manually routing complex, high-speed designs with many interconnected buses and multiple high pin-count devices. This resulted in prolonged and unpredictable design-cycle time, impacting project schedules and budgets. Cadence worked with several early adopter partners to help define the problem as well as drive and validate this unique solution.

"As a leading contributor to the development of the Cadence Global Route Environment technology, Motorola is pleased to be one of the first adopters of this next generation platform for printed circuit routing," said Jeff Underwood, principal staff printed circuit designer, Motorola. "By utilizing this new, enhanced routing environment, Motorola is enabling our engineers and designers to more accurately convey design intent, throughout the entire routing design process."

PCB designers have long sought a PCB environment that comprehends the global nature of the design environment that captures their design intent, provides decision feedback, and then intelligently and automatically performs design tasks adhering to their design intent. The new Global Route Environment technology offers exactly that. With the graphical interconnect flow planning architecture, it enables designers to create and define an intelligent abstraction of critical interfaces and capture interconnect design intent. This environment also leverages the global routing engine that allows designers to combine their knowledge and design intent with a hierarchical view of the design to plan the best interconnect solution possible.

"We are confident that the new Cadence interconnect flow within the Global Route Environment technology can significantly reduce redundancies in today's routing processes," said Jim Tafoya, PCB design technical manager, Sun Microsystems. "This is a ground-breaking effort and reinforces the commitment by Cadence to its PCB technology development cycle."

"Our early adopter customers have been critical in helping us understand product design requirements and then validate our unique solution," said Charlie Giorgetti, corporate vice president, Product Marketing, Cadence. "The Global Route Environment technology for Allegro PCB design helps customers quickly solve the interconnect challenges that previously would have taken weeks or even months of laborious work, threatening project schedules and budgets."

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### *CIM-Team and Zuken Launch the 2007 Version of E³.series, Including New Module: E³.formboard*

27 March 2007

CIM-Team and parent company, Zuken, the engineering consulting company; have announced the availability of E³.series 2007. The advancements in the latest version of the Windows-based electrical control design and documentation suite include functionality improvements relating to 3rd party integration and increased ease of use and productivity. Most notably, the new version signals the launch of a new formboard module for manufacturing cable harnesses

**Improvements in 3rd Party Compatibility**

Advancing integration within both the tool flow and 3rd party environments is top of the agenda for CIM-Team and Zuken. The latest version of E³.series includes enhancements to the certified SAP interface, along with support of 3D-MCAD data in STEP AP203/214 Format and MicroStation data. The improved SAP interface allows organizations to quickly and easily modify master records without having to enter the SAP environment. In addition, users can also edit component and classification material master data directly within E³.series using the online synchronization interface.

Having a common data entry area means that component SAP and design data only needs to be entered once, increasing product quality and design efficiency.

The new functionality to output panel data into STEP AP203/214 format enables transferring of design data to create three-dimensional models in 3D-MCAD environments. This allows the user to front load the completion of tasks such as collision checking with mechanical parts, saving valuable time downstream in the design process.

The bi-directional support of DGNdirect data for MicroStation has also been incorporated into the latest version of E³.series. This will allow organizations where MicroStation is dominantly used, to benefit

from E³.series' object orientated technology. Companies in the Civil Engineering, Oceanic and Utilities industries are set to benefit the most from this functionality.

**Enhanced Workflow with E3.formboard**

To support the custom wire and cable harness market, E³.formboard is being launched. This additional integrated module of the E³.series has been designed for the creation of nailboard displays required in producing wire and cable harnesses. E3.formboard makes it possible to create connector tables automatically, graphically display manufacturing and displayed lengths, apply automatic stretching and compressing to cables, as well as rotate cable branches. As with all other modules in the E³.series, the displayed view data of an object in a project with E3.formboard is always consistent with the schematic and additional documents.

**Ease of Use and Productivity**

Significant advancements to increased ease of use and productivity, come in the form of the ability to copy, insert and modify structural parts of a project. Using this functionality, entire panels can now be copied repeatedly and adapted to specific requirements. With larger installations, complete machinery and plant structures can be copied.

With "Shared Sheets" in E3.panel, specific regions of different panels can be displayed with individual scaling, making it significantly easier to wire between panels.

The ease of use enhancements detailed in this document cover just a small number of the 50 new functions now available within E³.series 2007.

Shipping of E³.series 2007 began in March '07; to find out more information visit http://www.cim-team.com/or http://www.zuken.com/e3.

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### *IQS Releases Version 6.80*

27 March 2007

IQS announced the release of Version 6.80 of IQS. "With the adoption of quality growing from quality control to full lifecycle quality management, release 6.80 from IQS helps us further address the growing end-to-end quality needs of our customers," said Michael Rapaport, CEO. The new version offers features that bridge the gap between engineering and manufacturing, reducing errors and driving out cost. Version 6.80 also has features that extend quality to non-traditional users, and improvements for Six-Sigma and Lean projects allowing quality to be an enterprise function, not simply an operational department.

Version 6.80 Early Adopter – Schefenacker Vision Systems weighs in on the new functionality to improve collaboration between engineering and manufacturing. “We are excited about IQS Version 6.8 functionality in the area of product change notices. We expect that the new flexibility and capability will allow us to better connect our Engineering and Manufacturing organizations. The efficiency gains here are extremely valuable,” said Bill Soule, Information Technology Manager at Schefenacker Vision Systems.

**Connecting Engineering and Manufacturing**

IQS release 6.80 introduces features that break down the barrier between engineering and manufacturing. Typically, a wealth of information like part specifications and characteristics, risk analysis and control plans are well developed in engineering, only to get vaulted and forgotten. Manufacturing then reinvents the data, or works from out of date information. The disconnect between engineering and manufacturing is a prime source of errors, rework, cost overruns, nonconformances and recalls. Version 6.80 provides features like improved engineering changes, cross departmental work-flows, FMEA authoring, custom views by supplier, product and plant, and brings engineering quality information logically into manufacturing. IQS systematizes the flow of engineering changes, document revisions, FMEA’s and control plans. The improved flow assures that everyone in the manufacturing process – operations, inspection, quality, purchasing and suppliers have the correct up-to-date information they need to do their job – correctly, the first time.

**Extending Quality to Non-Traditional Users**

IQS is further expanding quality to non-traditional enterprise users. Release 6.8 provides user interface flexibility and tailoring to assure that quality is easily accessible to everyone from engineering and suppliers to operations. The new release offers a fully customizable user interface and menu structure to make quality practices friendlier to purchasing, engineering and non-traditional quality users. It allows dynamic views of tasks and issues by product, supplier, and customer creating usable quality information for the entire product team.

**Supporting Program Launch Management – MS Project Integration**

IQS tracks the nitty gritty details it takes to execute a project. For each task that is typically tracked in a project plan, IQS has instructions, checklists and assignments at the checklist level and a wealth of information to assure that the activity is performed correctly, and linked to the next step. IQS provides program managers visibility and traceability to assure that when an activity is marked as “done” it has been done correctly. Because IQS tracks at a very fine level of detail, linking IQS into project management gives a program manager greater predictability in their projections. They are able to understand accurate activity completion, the nature of bottlenecks, alternatives to issues, and in short – do what needs to be done to bring their program in on time. In version 6.80 IQS is integrated with MS Project, passing projects back and forth, and flowing the wealth of IQS information up to program managers.

**Six-Sigma, Lean and As-Built – Core Functions also Enhanced**

Release 6.8 offers many additions and enhancements to its core quality functionality. For Six-Sigma and Lean projects, additional data is being tracked; e.g. scope, impact, cost, benefit etc.. The enhancements provide turnkey tracking of Lean and Six-Sigma projects from inside IQS. For clients who create assembled parts, there is a new “As Built” option that allows traceability and verification for all serial numbers and components of a final assembly. In addition to removing hours of manual verification work, and the inevitable errors, if there is warranty work down the road, “As Built” can pinpoint who, what, when and where the product was manufactured, minimizing the impact of warranty work and saving countless hours and dollars.

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### *Magma FineSim SPICE Supports STARC HiSIM Model with Proven 20x Faster Circuit Simulation and Nearly Exact Correlation to Silicon*

26 March 2007

Magma® Design Automation Inc. and the Semiconductor Technology Academic Research Center (STARC), a research consortium co-founded by 11 major Japanese semiconductor companies, announced FineSim™ SPICE support for the HiSIM model. STARC leveraged the FineSim SPICE proprietary Native Parallel Technology™ to implement the model, achieving 20x faster circuit simulation on STARC's 90-nanometer (nm) Star Shuttle analog intellectual property (IP) and nearly exact correlation to silicon.

STARC's mission is to contribute to the growth of the Japanese semiconductor industry by developing leading-edge system-on-a-chip (SoC) design technologies. "STARC's goal is to seek out new and effective technologies and FineSim's breakthrough in Native Parallel Technology captured our attention," said Yoshiharu Furui, deputy general manager of STARC. "FineSim SPICE has impressed us by rapidly implementing our latest HiSIM model while achieving over 20x faster circuit simulation of our analog IP. Also we verified that FineSim SPICE accurately correlated with our analog IP in silicon manufactured by our 90-nm Star Shuttle.”

HiSIM (Hiroshima-University STARC IGFET Model) is a surface-potential-based circuit simulation model for MOSFETs which Hiroshima University developed in collaboration with STARC. The Star Shuttle is the first standard 90-nm process-based prototype manufacturing service in Japan to develop low-power SoC design technologies. Star Shuttle was established as a result of the ASUKA Project run jointly by Japan Electronics and Information Technology Industries Association (JEITA). STARC assumed management of Star Shuttle in 2005.

FineSim SPICE is a SPICE-level simulation analysis tool that incorporates transistor-level simulation analysis capabilities for mixed digital and analog designs. FineSim SPICE contains a full SPICE simulation engine with distributed processing that enables customers to simulate large-scale, mixed-signal SoCs at the transistor level. By providing increased speed and capacity while maintaining full SPICE accuracy, FineSim SPICE enables designers to simulate advanced circuits – such as PLLs, ADCs (analog-to-digital converters), DACs (digital-to-analog converters) and gigahertz SERDES

(SERializer/DESerializer) – that they previously would not even attempt using slower, traditional SPICE simulators.

"With the latest HiSIM model and FineSim SPICE's significant speed, capacity and silicon-accuracy advantages, STARC and Magma provide advanced design technologies that reduce time to market," said Suk Lee, general manager of Magma's Custom Design Business Unit. "We're pleased to partner with STARC to support the growth of the semiconductor industry in Japan."

Visit Magma Design Automation on the web at http://www.magma-da.com/and http://www.magma-da.co.jp/.

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### *Mentor Graphics Announces Subsystem Intellectual Property Launch with First Delivery of Integrated USB Solution*

26 March 2007

Mentor Graphics Corporation announced a technology launch of subsystem intellectual property (IP), beginning with the industry's first USB subsystem solution from a single-source EDA provider. Mentor Graphics is the only EDA company that develops its own digital controller, hardware PHY (physical layer), and embedded software IP to deliver an integrated and verified IP solution for today's complex electronics designs. The end result is faster design creation, improved overall product quality, and faster time-to-market, with particular benefit for the high-demand consumer electronics market.

According to a recent Fabless Semiconductor Association (FSA) discussion on IP ("IP-Building an Efficient Ecosystem," Oct. 11, 2006), third-party IP adopted for today's electronic designs can be costly due to problems encountered with the integration of the digital IP, analog PHY and embedded software IP since these typically come from various IP providers. The FSA discussion indicated that associated costs of identifying, sourcing and verifying semiconductor IP required to create a complete and integrated IP subsystem can greatly impact the total cost of development.

"Mentor is a leader in providing standards-based digital IP and embedded software and verification solutions and we believe that providing a fully integrated and verified subsystem IP solution will support the industry moving forward in 2007," said Kathy Werner, VSI Alliance president. "Mentor's leadership in USB IP provides tremendous advantages for customers developing next-generation products with this offering."

"This past year, many of our large customers have experienced integration issues –primarily with digital controllers and embedded software IP – delaying their consumer product introductions. To help remove these integration challenges, we are responding to customer requirements with our Subsystem IP solution," stated Bill Martin, Mentor Graphics IP Division general manager. "As the only EDA company to offer all three technologies - digital, analog and embedded software IP - we enable our customers to save critical time and resources with a fully-integrated and verified IP block. Our complete USB

Subsystem IP solution removes hidden costs for customers who are faced with the complexities of hardware and software design integration."

**USB Subsystem Pricing and Availability**

The Mentor Graphics fully-integrated and verified USB Subsystem IP is available now. For more information, go to the company website: http://www.mentor.com/IPor contact a Mentor Graphics local sales office for specific pricing details. Subsystem IP products presently under development, with availability in 2007, include SATA and Ethernet solutions—furthering Mentor's technology leadership in these two applications areas.

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### *Mori Seiki and PartMaker Partner to Provide Seamless Programming Solutions*

23 March 2007

Delcam's PartMaker Inc. division and Mori Seiki have partnered to provide Mori Seiki users a programming solution for the new Mori Seiki NT Turn-Mill centre. PartMaker CADCAM software, in addition, supports the full line of Mori Seiki multi-axis lathes including the Mori Seiki ZT, MT, NL, DL and SL models among others.

As part of the cooperation between PartMaker and Mori Seiki on the new NT model, Mori Seiki engineers have tested NC program output generated by PartMaker for programming various machining scenarios on the Mori Seiki NT. These machining scenarios include various turning and milling operations, canned cycle routines and synchronous machining combinations using the machine's articulating B-axis head and lower turret.

"The collaboration between Mori Seiki and PartMaker is a unique one because it allows Mori Seiki NT users to have a high degree of confidence in the results they can achieve with PartMaker even though the Mori Seiki NT model is still a relatively new model in the field," says Hanan Fishman, PartMaker Inc. President. "Mori Seiki has shown tremendous vision in making a proactive investment in testing PartMaker output for the NT machine so its users can be assured of the results they achieve when implementing PartMaker for this machine."

"By working with leading CAM software vendors such as PartMaker" adds Dr. Fujishima, Development Director for Mori Seiki, "we are able to give our customers the assurance that there is a programming solution available to meet their needs when investing in our latest generation NT range of our multi-tasking machine tools."

**More on PartMaker**

PartMaker is a Knowledge Based Machining system, allowing it to provide substantial gains in programming efficiency by remembering the tools, material and process information necessary to

machine individual part features. PartMaker thus relieves the user from re-entering the same features information for subsequent parts. It also improves productivity by placing the emphasis on tool management functions.

The software supports the full range of CNC applications including CNC Mills, Lathes, Wire EDMs, multi-tasking Turn-Mill Centers and CNC Swiss-type lathes.

PartMaker pioneered a Visual Programming Approach for programming multi-axis lathes with live tooling, a system for which it holds two U.S. patents. PartMaker assures quicker learning and easier use. It makes an extensive use of pictures to help the user describe tools, part features and machining data. Synchronization of tools working on multiple spindles is achieved by a few mouse clicks.

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### *POLYFLOW 3.11 Extends Its Complex Physics in a User-Friendly Way*

29 March 2007

ANSYS, Inc. announced the release of POLYFLOW® 3.11 software for the analysis of polymer processing and glass forming. This new version of POLYFLOW further extends the vast library of viscoelastic models by adding the Leonov viscoelastic model and a simplified viscoelastic model for extrusion. For thermoforming and blow molding applications, POLYFLOW 3.11 offers a simple thermo-mechanical stress capability to calculate deformations during cooling. Finally, key enhancements to the 3-D adaptive meshing technique make the simulation of glass pressing and blowing faster and more robust than ever before. POLYFLOW technologies are now part of the ANSYS® suite, from the company's acquisition of Fluent Inc. in 2006. Companies who use the software have found that the quality of extruded, blown and thermoformed products -- such as rubber tires, ceramics and glass -- is greatly improved by running trial and error processes with POLYFLOW rather than on the production line.

"This new release of POLYFLOW offers a nice balance between our advanced technology, including new physically complex models, and a growing demand from industries involved in manufacturing tasks," says Thierry Marchal, industry marketing director for materials and consumer care at ANSYS, Inc. "For the latter, new features such as the simplified viscoelastic model for extrusion, transparent and robust 3-D adaptive remeshing techniques, or the extension of the polymer forming simulations to the cooling stage, either via POLYFLOW or through advanced structural codes such as ANSYS, will help them to speed up their design process and improve product quality."

POLYFLOW software has a library of viscoelastic and complex rheology models, and the addition of the two new viscoelastic models completes the highly advanced level of capability. The Leonov model is recognized for its ability to accurately reproduce the complexity of the viscoelastic behavior of rubber filled with carbon black, for example, typical in the tire industry. Additionally, the simplified viscoelastic model for extrusion is able to accurately reproduce large die swell typical of viscoelastic flow while running much faster simulations and requiring much less memory than traditional viscoelastic models. Benchmarking this new capability against traditional viscoelastic models revealed that the simplified

viscoelastic model for extrusion requires six times less memory and could run 15 times faster for typical extrusion processes involving free surface.

Polymer thermoforming and blow molding is an application of growing importance to POLYFLOW users. Beyond the need to simulate the forming process itself, the industry now is demanding tools to calculate deformation and stress after cooling. POLYFLOW 3.11 software offers two new options. First, it creates a 3-D geometry out of the deformed shell and the calculated thickness that then can be used for advanced shrinkage and warpage simulation with structural codes. Second, it allows the user to conduct some simple thermo-mechanical stress and deformation analyses directly in POLYFLOW to obtain a qualitatively good estimation of these quantities.

Glass forming applications, whether related to gob forming, bottle blowing, pressing or making drinking glass, increasingly use numerical simulation to provide better insight into the complex deformations and thermal patterns that occur during the process. These simulations are extremely challenging since they involve very large deformations coupled with steep thermal gradients. POLYFLOW 3.11 enhancements to its 3-D adaptive meshing techniques help maintain a good mesh and results quality while reducing the computational time.

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### *PTC Launches Product Development Process Framework That Links PLM Investments to the Achievement of Critical Business Objectives*

29 March 2007

PTC announced the availability of a comprehensive process framework that consists of industry-specific product development process landscapes. The intent of this framework is to help discrete manufacturers in multiple industries understand the linkage between product development process improvements, PLM technology investments, and business value.

One of the most daunting challenges for a product development organization today is how to achieve the maximum benefit from its limited technology budget. This is especially true for organizations in highly competitive and highly regulated industries that have intense pressure on cost reduction, time to market, and compliance. Further complicating this equation can be the question of how, when, and where to deploy investments in technology in order to best realize specific business initiatives and gain true competitive differentiation. While the primary benefit from PLM technology is process optimization, organizations that lack a deep understanding of internal process improvement goals risk making unfocused technology investments that can lead to frustration and fail to achieve their full potential.

Over the past 20 years, PTC has worked with leading product development companies in a variety of vertical industries to achieve a wide range of business goals. As a result, PTC recognizes that in addition to sensible technology investments, the most successful organizations have also developed best practices and sound business processes in critical product development areas. Subsequently, PTC has developed a tool based on decades of experience that helps customers realize value from PLM. Using the tool, PTC helps companies align and prioritize business and product development goals with industry-specific

process improvements. The result is a rational technology adoption path that is tailored to each individual organization's objectives. The central communication vehicle for our process framework is the new PTC Value Roadmap. The Value Roadmap is a fully configurable, interactive software application that matches an organization's unique goals with vertical industry best practices and delivers a dynamically created, customer-specific report.

"At Emhart Glass, we are committed to delivering the highest quality equipment, controls, and parts to our customers so that they can meet their business objectives. While maintaining this focus, we must also continue to improve our speed and efficiency in the development of new products. Therefore, when making PLM technology decisions, we need to consider more than just new features," said Steven Pinkerton, vice president of RD&E, Emhart Glass. "We need to think about how to improve our product development processes. With help from PTC's Value Roadmap, we can focus our investments on those areas that will have the most impact on our business goals."

Currently, PTC has created 7 industry/audience-specific process landscapes with plans for 2 additional in the coming months. Each of the 7 process landscape incorporates between 11 and 24 critical product development processes. These detailed process landscapes contain comprehensive information about typical product development processes, including a model used to indicate a company's current level of maturity for a given process as well as the targeted maturity level they would like to achieve.

"Aligning technology investments to best practices and process improvements is a key strategic focus for our customers," said Jim Heppelmann, executive vice president and chief product officer, PTC. "We have developed this comprehensive set of process-oriented information, inter-relational value drivers and a complex configuration tool as the result of years of research. Technology investments represent potential value to a customer, however we have found that customers who properly align process and technology optimization can more readily realize that value and achieve significant competitive differentiation and industry leadership."

Interactive demonstrations and consultation sessions are currently available for product development practitioners to learn more about the Value Roadmap at http://www.ptc.com/solutions/global_product_development/value_roadmap.htm.

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### *Synopsys IC Compiler Enables Fully Automated 65-Nanometer Implementation Flow for ARM Cortex-A8 Processor*

28 March 2007

Synopsys, Inc. and ARM announced the immediate availability of a fully automated implementation flow enabled by Synopsys IC Compiler for high-performance and low-power applications. The Galaxy™ Design Platform RTL-to-GDSII flow for the synthesizable ARM® Cortex™-A8 processor includes DC Topographical technology, the DFT MAX solution and the latest physical design technology available in IC Compiler. This portable Synopsys flow, along with the ARM processor and physical IP, delivers a 5-10x improvement in designer productivity compared to the original optimized, semi-custom approach.

The flow has also delivered more than 1000 DMIPS at 500MHz performance in a 65-nanometer (nm) low-power process technology and is capable of achieving over 1700 DMIPS at 850MHz for advanced consumer applications when targeted at high-performance 65-nm process technologies.

"The ARM and Synopsys technical collaboration has resulted in a widely deployable implementation flow for the Cortex-A8 processor with clear time-to-market savings," said John Cornish, vice president of marketing, Processor Division, ARM. "With many customers focused on increased productivity and meeting tight schedules, the Synopsys Galaxy implementation flow for the Cortex-A8 processor will enable customers to achieve a high-performance and low-power design point with a small team and limited resource investment."

The Cortex-A8 processor, ARM's first high-end application processor based on the ARMv7 architecture, features support for TrustZone® technology, Thumb®-2 instructions, Jazelle®-RCT technology and the powerful ARM NEON™ signal processing extensions that are targeted at the next-generation enriched multimedia and gaming platforms.

Building on experience from the optimized semi-custom implementation design flow for the Cortex-A8 processor, ARM and Synopsys have created a fully automated synthesizable Galaxy implementation flow. The new approach enables a small team of engineers with a standard ASIC design background to achieve the required performance for next-generation high-performance, low-power applications within three months. The easy-to-use implementation flow leverages ARM physical IP optimized for the Cortex-A8 processor while enabling broader design portability across both libraries and process technologies (90-nm, 65-nm and 45-nm).

"The key to addressing high-performance and low-power needs of the wireless and consumer markets is the concurrent optimization capability in design tools," said Bijan Kiani, vice president of marketing, Synopsys Implementation Group. "Delivering a 500 MHz low-power Cortex-A8 processor and an 850 MHz high-performance version is a strong testimonial to the strength of our technology and close collaboration with ARM."

The automated implementation flow for the synthesizable Cortex-A8 processor was validated using the ARM Advantage™-HS standard cells and optimized Advantage Random Access Memory (RAM) instances for 65-nm LP technology to achieve both high performance and low power. The combination of an easy-to-use implementation flow, a high-quality processor and physical IP enables customers to deliver proven results with best-in-class productivity. Designers can combine the flow with the ARM physical IP, optimized for the Cortex-A8 processor, or use the flow with their own physical IP libraries.

ARM and Synopsys, a member of the ARM Connected Community, will present a technical paper on this flow at the San Jose Synopsys Users Group (SNUG) on Monday, April 2nd 2007 and at the Design, Automation and Test (DATE) conference on Wednesday, April 18th 2007.

**Availability**

The automated implementation flow for the Cortex-A8 processor (scripts and documentation) is available immediately from Synopsys. In addition, Synopsys offers consulting services to help accelerate the adoption and implementation of advanced methodologies, including high-performance and low-power design techniques for ARM processor-based designs, including those based on the Cortex-A8 processor. The synthesizable Cortex-A8 processor, Advantage-HS standard cells and optimized Advantage RAM instances for target 65LP processes are immediately available from ARM.

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### *UGS' New NX CAM Express Program Increases Machine Tool Value for SMBs*

27 March 2007

UGS Corp. announced the NX CAM Express "Delivering Machine Tool Value" program, which provides application-specific CAM software to small and medium sized businesses (SMB) manufacturers with new machine tools. NX CAM Express, a full function numerical control (NC) programming application, is the CAM component of the UGS Velocity Series™ portfolio.

The program emphasizes the role of a comprehensive CAM system in supporting the latest machine tool technology. Investments in new advanced machine tool technology typically generate immediate returns on investment (ROI) for manufacturers. UGS is working along side machine tool vendors to provide an effective CAM system that supports the full capability of the latest advanced machines. This collaboration enables UGS to provide a CAM system that supports the latest machines along with post processing, controller options and machine configurations as well as joint customer support to help customers reach their highest productivity.

"Our machine tool customers purchase the latest technology in machine tools in order to gain the efficiencies that drive bottom line profits," said Tom Glisczinski. president, Applied CIM (UGS partner). "These efficiencies are realized by process optimization, NC Programming and knowledgeable vendor support. We view NX CAM Express from UGS as the most capable and comprehensive system offering for our customers to complete their machine tool investments."

The "Delivering Machine Tool Value" program focuses on helping manufacturers derive more value from their machine tools by increasing utilization and optimization for the technological features for which they were purchased. This is important to key machining industries, including:

In the mold and die industry, high speed machines are the driving technology. An investment in high speed milling machines demands NC programs that are able to drive the new machines effectively. NX CAM Express has the capability to efficiently program and optimize high speed roughing, re-roughing, and finishing.

In the production machining industry, multi-function turning centers and mill-turns dramatically reduce cycle times when properly utilized. These highly capable and multi-faceted machines require process

planning and programming over the full spectrum of milling and turning. NX CAM Express provides the synchronization and simulation designed specifically for these machines.

In the machining of complex parts, 5-axis machinery is the key to manufacturing complex geometry cases. From aero structures to turbo machinery to medical applications, 5-axis machines are the key to set-up reduction and efficient machining complex parts. NX CAM Express provides highly capable 5-axis NC programming designed to optimize around this technology.

NX CAM Express has the in-depth capabilities to address the programming requirements of these advanced, more productive machines. As part of the Velocity Series portfolio, it is focused on ease of use, fast deployment and scalability so users can take advantage of its capabilities quickly and easily as their needs demand.

To learn more about the “Delivering Machine Tool Value” program, visit http://www.ugs.com/dmtv.

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